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PRELIMINARY

80C186EB/80C188EB AND 80L186EB/80L188EB 16-BIT HIGH-INTEGRATION EMBEDDED PROCESSORS

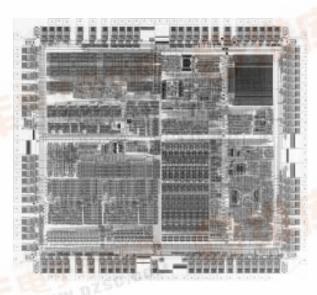
Full Static Operation

- True CMOS Inputs and Outputs
- Integrated Feature Set
 - Low-Power Static CPU Core
 - Two Independent UARTs each with an Integral Baud Rate Generator
 - Two 8-Bit Multiplexed I/O Ports - Programmable Interrupt Controller
 - Three Programmable 16-Bit
 - Timer/Counters
 - Clock Generator
 - Ten Programmable Chip Selects with Integral Wait-State Generator
 - Memory Refresh Control Unit
 - System Level Testing Support (ONCE Mode)
- Direct Addressing Capability to 1 Mbyte Memory and 64 Kbyte I/O
- Speed Versions Available (5V):
 - 25 MHz (80C186EB25/80C188EB25)
 - 20 MHz (80C186EB20/80C188EB20)
 - 13 MHz (80C186EB13/80C188EB13)

- Available in Extended Temperature Range (-40°C to +85°C)
 - Speed Versions Available (3V):

 - 8 MHz (80L186EB8/80L188EB8)
 - 8 MHZ (8021802B6/8021882B6)
- Low-Power Operating Modes:
 Idle Mode Freezes CPU Clocks but keeps Peripherals Active
 - Powerdown Mode Freezes All Internal Clocks
- Supports 80C187 Numeric Coprocessor Interface (80C186EB PLCC Only)
 - Available In:
 - 80-Pin Quad Flat Pack (QFP)
 84-Pin Plastic Leaded Chip Carrier (PLCC)
 - 80-Pin Shrink Quad Flat Pack (SQFP)

The 80C186EB is a second generation CHMOS High-Integration microprocessor. It has features that are new to the 80C186 family and include a STATIC CPU core, an enhanced Chip Select decode unit, two independent Serial Channels, I/O ports, and the capability of Idle or Powerdown low power modes.





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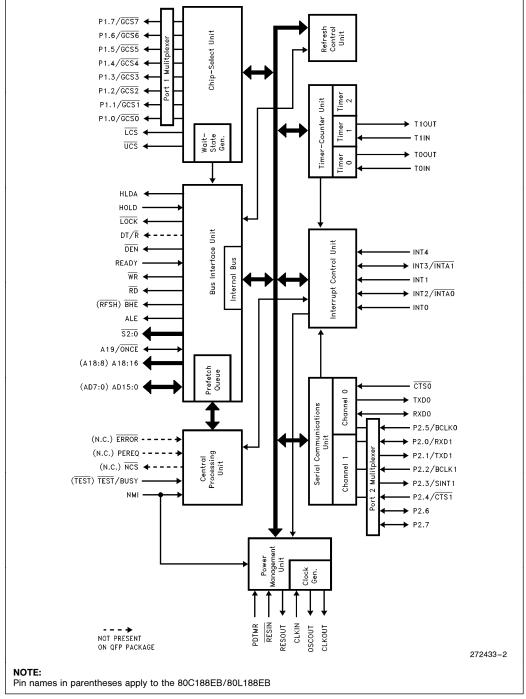


Figure 1. 80C186EB/80C188EB Block Diagram

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INTRODUCTION

Unless specifically noted, all references to the 80C186EB apply to the 80C188EB, 80L186EB, and 80L188EB. References to pins that differ between the 80C186EB/80L186EB and the 80C186EB/80L188EB are given in parentheses. The "L" in the part number denotes low voltage operation. Physically and functionally, the "C" and "L" devices are identical.

The 80C186EB is the first product in a new generation of low-power, high-integration microprocessors. It enhances the existing 186 family by offering new features and new operating modes. The 80C186EB is object code compatible with the 80C186XL/ 80C188XL microprocessors.

The 80L186EB is the 3V version of the 80C186EB. The 80L186EB is functionally identical to the 80C186EB embedded processor. Current 80C186EB users can easily upgrade their designs to use the 80L186EB and benefit from the reduced power consumption inherent in 3V operation.

The feature set of the 80C186EB meets the needs of low power, space critical applications. Low-Power applications benefit from the static design of the CPU core and the integrated peripherals as well as low voltage operation. Minimum current consumption is achieved by providing a Powerdown mode that halts operation of the device, and freezes the clock circuits. Peripheral design enhancements ensure that non-initialized peripherals consume little current.

Space critical applications benefit from the integration of commonly used system peripherals. Two serial channels are provided for services such as diagnostics, inter-processor communication, modem interface, terminal display interface, and many others. A flexible chip select unit simplifies memory and peripheral interfacing. The interrupt unit provides sources for up to 129 external interrupts and will prioritize these interrupts with those generated from the on-chip peripherals. Three general purpose timer/counters and sixteen multiplexed I/O port pins round out the feature set of the 80C186EB.

Figure 1 shows a block diagram of the 80C186EB/ 80C188EB. The Execution Unit (EU) is an enhanced 8086 CPU core that includes: dedicated hardware to speed up effective address calculations, enhance execution speed for multiple-bit shift and rotate instructions and for multiply and divide instructions, string move instructions that operate at full bus bandwidth, ten new instruction, and fully static operation. The Bus Interface Unit (BIU) is the same as that found on the original 186 family products, except the queue status mode has been deleted and buffer interface control has been changed to ease system design timings. An independent internal bus is used to allow communication between the BIU and internal peripherals.

CORE ARCHITECTURE

Bus Interface Unit

The 80C186EB core incorporates a bus controller that generates local bus control signals. In addition, it employs a HOLD/HLDA protocol to share the local bus with other bus masters.

The bus controller is responsible for generating 20 bits of address, read and write strobes, bus cycle status information, and data (for write operations) information. It is also responsible for reading data off the local bus during a read operation. A READY input pin is provided to extend a bus cycle beyond the minimum four states (clocks).

The local bus controller also generates two control signals ($\overline{\text{DEN}}$ and DT/R) when interfacing to external transceiver chips. (Both $\overline{\text{DEN}}$ and DT/R are available on the PLCC devices, only $\overline{\text{DEN}}$ is available on the QFP and SQFP devices.) This capability allows the addition of transceivers for simple buffering of the multiplexed address/data bus.

Clock Generator

The processor provides an on-chip clock generator for both internal and external clock generation. The clock generator features a crystal oscillator, a divideby-two counter, and two low-power operating modes.

The oscillator circuit is designed to be used with either a **parallel resonant** fundamental or third-overtone mode crystal network. Alternatively, the oscillator circuit may be driven from an external clock source. Figure 2 shows the various operating modes of the oscillator circuit.

The crystal or clock frequency chosen must be twice the required processor operating frequency due to the internal divide-by-two counter. This counter is used to drive all internal phase clocks and the external CLKOUT signal. CLKOUT is a 50% duty cycle processor clock and can be used to drive other system components. All AC timings are referenced to CLKOUT.

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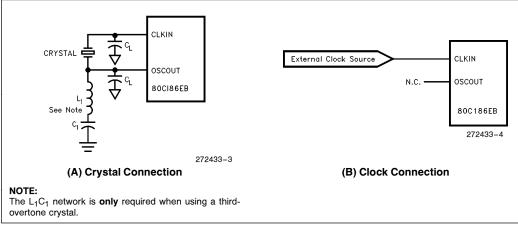


Figure 2. Clock Configurations

The following parameters are recommended when choosing a crystal:

Temperature Range:	Application Specific
ESR (Equivalent Series Resistar	ice): $40\Omega \max$
C0 (Shunt Capacitance of Crysta	d): 7.0 pF max
C _L (Load Capacitance):	20 pF ± 2 pF
Drive Level:	1 mW max

80C186EB PERIPHERAL ARCHITECTURE

The 80C186EB has integrated several common system peripherals with a CPU core to create a compact, yet powerful system. The integrated peripherals are designed to be flexible and provide logical interconnections between supporting units (e.g., the interrupt control unit supports interrupt requests from the timer/counters or serial channels).

The list of integrated peripherals includes:

- 7-Input Interrupt Control Unit
- 3-Channel Timer/Counter Unit
- 2-Channel Serial Communications Unit
- 10-Output Chip-Select Unit
- I/O Port Unit
- Refresh Control Unit
- Power Management Unit

The registers associated with each integrated periheral are contained within a 128 x 16 register file called the Peripheral Control Block (PCB). The PCB can be located in either memory or I/O space on any 256 Byte address boundary.

Figure 3 provides a list of the registers associated with the PCB. The Register Bit Summary at the end of this specification individually lists all of the registers and identifies each of their programming attributes.

Interrupt Control Unit

The 80C186EB can receive interrupts from a number of sources, both internal and external. The interrupt control unit serves to merge these requests on a priority basis, for individual service by the CPU. Each interrupt source can be independently masked by the Interrupt Control Unit (ICU) or all interrupts can be globally masked by the CPU.

Internal interrupt sources include the Timers and Serial channel 0. External interrupt sources come from the five input pins INT4:0. The NMI interrupt pin is not controlled by the ICU and is passed directly to the CPU. Although the Timer and Serial channel each have only one request input to the ICU, separate vector types are generated to service individual interrupts within the Timer and Serial channel units.

Timer/Counter Unit

The 80C186EB Timer/Counter Unit (TCU) provides three 16-bit programmable timers. Two of these are highly flexible and are connected to external pins for control or clocking. A third timer is not connected to any external pins and can only be clocked internally. However, it can be used to clock the other two timer channels. The TCU can be used to count external events, time external events, generate non-repetitive waveforms, generate timed interrupts. etc.



PCB Offset	Function	PCB Offset	Function	PCB Offset	Function	PCB Offset	Function
00H	Reserved	40H	Timer2 Count	80H	GCS0 Start	СОН	Reserved
02H	End Of Interrupt	42H	Timer2 Compare	82H	GCS0 Stop	C2H	Reserved
04H	Poll	44H	Reserved	84H	GCS1 Start	C4H	Reserved
06H	Poll Status	46H	Timer2 Control	86H	GCS1 Stop	C6H	Reserved
08H	Interrupt Mask	48H	Reserved	88H	GCS2 Start	C8H	Reserved
0AH	Priority Mask	4AH	Reserved	8AH	GCS2 Stop	CAH	Reserved
0CH	In-Service	4CH	Reserved	8CH	GCS3 Start	ССН	Reserved
0EH	Interrupt Request	4EH	Reserved	8EH	GCS3 Stop	CEH	Reserved
10H	Interrupt Status	50H	Port 1 Direction	90H	GCS4 Start	D0H	Reserved
12H	Timer Control	52H	Port 1 Pin	92H	GCS4 Stop	D2H	Reserved
14H	Serial Control	54H	Port 1 Control	94H	GCS5 Start	D4H	Reserved
16H	INT4 Control	56H	Port 1 Latch	96H	GCS5 Stop	D6H	Reserved
18H	INT0 Control	58H	Port 2 Direction	98H	GCS6 Start	D8H	Reserved
1AH	INT1 Control	5AH	Port 2 Pin	9AH	GCS6 Stop	DAH	Reserved
1CH	INT2 Control	5CH	Port 2 Control	9CH	GCS7 Start	DCH	Reserved
1EH	INT3 Control	5EH	Port 2 Latch	9EH	GCS7 Stop	DEH	Reserved
20H	Reserved	60H	Serial0 Baud	A0H	LCS Start	E0H	Reserved
22H	Reserved	62H	Serial0 Count	A2H	LCS Stop	E2H	Reserved
24H	Reserved	64H	Serial0 Control	A4H	UCS Start	E4H	Reserved
26H	Reserved	66H	Serial0 Status	A6H	UCS Stop	E6H	Reserved
28H	Reserved	68H	Serial0 RBUF	A8H	Relocation	E8H	Reserved
2AH	Reserved	6AH	Serial0 TBUF	AAH	Reserved	EAH	Reserved
2CH	Reserved	6CH	Reserved	ACH	Reserved	ECH	Reserved
2EH	Reserved	6EH	Reserved	AEH	Reserved	EEH	Reserved
30H	Timer0 Count	70H	Serial1 Baud	B0H	Refresh Base	F0H	Reserved
32H	Timer0 Compare A	72H	Serial1 Count	B2H	Refresh Time	F2H	Reserved
34H	Timer0 Compare B	74H	Serial1 Control	B4H	Refresh Control	F4H	Reserved
36H	Timer0 Control	76H	Serial1 Status	B6H	Reserved	F6H	Reserved
38H	Timer1 Count	78H	Serial1 RBUF	B8H	Power Control	F8H	Reserved
3AH	Timer1 Compare A	7AH	Serial1 TBUF	BAH	Reserved	FAH	Reserved
3CH	Timer1 Compare B	7CH	Reserved	BCH	Step ID	FCH	Reserved
3EH	Timer1 Control	7EH	Reserved	BEH	Reserved	FEH	Reserved

Figure 3. Peripheral Control Block Registers

Serial Communications Unit

The Serial Control Unit (SCU) of the 80C186EB contains two independent channels. Each channel is identical in operation except that only channel 0 is supported by the integrated interrupt controller (channel 1 has an external interrupt pin). Each channel has its own baud rate generator that is independent of the Timer/Counter Unit, and can be internally or externally clocked at up to one half the 80C186EB operating frequency.

Independent baud rate generators are provided for each of the serial channels. For the asynchronous modes, the generator supplies an 8x baud clock to both the receive and transmit register logic. A 1x baud clock is provided in the synchronous mode.

Chip-Select Unit

The 80C186EB Chip-Select Unit (CSU) integrates logic which provides up to ten programmable chipselects to access both memories and peripherals. In addition, each chip-select can be programmed to automatically insert additional clocks (wait-states) into the current bus cycle and automatically terminate a bus cycle independent of the condition of the READY input pin.

I/O Port Unit

The I/O Port Unit (IPU) on the 80C186EB supports two 8-bit channels of input, output, or input/output operation. Port 1 is multiplexed with the chip select pins and is output only. Most of Port 2 is multiplexed with the serial channel pins. Port 2 pins are limited to either an output or input function depending on the operation of the serial pin it is multiplexed with.

Refresh Control Unit

The Refresh Control Unit (RCU) automatically generates a periodic memory read bus cycle to keep dynamic or pseudo-static memory refreshed. A 9-bit counter controls the number of clocks between refresh requests.

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A 12-bit address generator is maintained by the RCU and is presented on the A12:1 address lines during the refresh bus cycle. Address bits A19:13 are programmable to allow the refresh address block to be located on any 8 Kbyte boundary.

Power Management Unit

The 80C186EB Power Management Unit (PMU) is provided to control the power consumption of the device. The PMU provides three power modes: Active, Idle, and Powerdown.

Active Mode indicates that all units on the 80C186EB are functional and the device consumes maximum power (depending on the level of peripheral operation). Idle Mode freezes the clocks of the Execution and Bus units at a logic zero state (all peripherals continue to operate normally).

The Powerdown mode freezes all internal clocks at a logic zero level and disables the crystal oscillator. All internal registers hold their values provided V_{CC} is maintained. Current consumption is reduced to just transistor junction leakage.

80C187 Interface (80C186EB Only)

The 80C186EB (PLCC package only) supports the direct connection of the 80C187 Numerics Coprocessor.

ONCE Test Mode

To facilitate testing and inspection of devices when fixed into a target system, the 80C186EB has a test mode available which forces all output and input/ output pins to be placed in the high-impedance state. ONCE stands for "ON Circuit Emulation". The ONCE mode is selected by forcing the A19/ONCE pin LOW (0) during a processor reset (this pin is weakly held to a HIGH (1) level) while RESIN is active.



PACKAGE INFORMATION

This section describes the pins, pinouts, and thermal characteristics for the 80C186EB in the Plastic Leaded Chip Carrier (PLCC) package, Shrink Quad Flat Pack (SQFP), and Quad Flat Pack (QFP) package. For complete package specifications and information, see the Intel Packaging Outlines and Dimensions Guide (Order Number: 231369).

Prefix Identification

With the extended temperature range, operational characteristics are guaranteed over the temperature range corresponding to -40° C to $+85^{\circ}$ C ambient. Package types are identified by a two-letter prefix to the part number. The prefixes are listed in Table 1.

Table 1. Prefix Identification

Prefix	Note	Package Type	Temperature Type
ΤN		PLCC	Extended
TS		QFP (EIAJ)	Extended
SB	1	SQFP	Extended/Commercial
Ν	1	PLCC	Commercial
S	1	QFP (EIAJ)	Commercial

NOTE:

1. The 5V 25 MHz and 3V 16 MHz versions are only available in commercial temperature range corresponding to 0°C to $+70^{\circ}$ C ambient.

Pin Descriptions

Each pin or logical set of pins is described in Table 3. There are three columns for each entry in the Pin Description Table.

The **Pin Name** column contains a mnemonic that describes the pin function. Negation of the signal name (for example, $\overline{\text{RESIN}}$) denotes a signal that is active low.

The **Pin Type** column contains two kinds of information. The first symbol indicates whether a pin is power (P), ground (G), input only (I), output only (O) or input/output (I/O). Some pins have multiplexed functions (for example, A19/S6). Additional symbols indicate additional characteristics for each pin. Table 2 lists all the possible symbols for this column.

The **Input Type** column indicates the type of input (Asynchronous or Synchronous).

Asynchronous pins require that setup and hold times be met only in order to guarantee *recognition* at a particular clock edge. Synchronous pins require that setup and hold times be met to guarantee proper *operation.* For example, missing the setup or hold time for the SRDY pin (a synchronous input) will result in a system failure or lockup. Input pins may also be edge- or level-sensitive. The possible characteristics for input pins are S(E), S(L), A(E) and A(L).

The **Output States** column indicates the output state as a function of the device operating mode. Output states are dependent upon the current activity of the processor. There are four operational states that are different from regular operation: bus hold, reset, Idle Mode and Powerdown Mode. Appropriate characteristics for these states are also indicated in this column, with the legend for all possible characteristics in Table 2.

The **Pin Description** column contains a text description of each pin.

As an example, consider AD15:0. I/O signifies the pins are bidirectional. S(L) signifies that the input function is synchronous and level-sensitive. H(Z) signifies that, as outputs, the pins are high-impedance upon acknowledgement of bus hold. R(Z) signifies that the pins float during reset. P(X) signifies that the pins retain their states during Powerdown Mode.

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Table 2. Pin Description Nomenclature								
Symbol	Description							
Р	Power Pin (Apply + V _{CC} Voltage)							
G	Ground (Connect to V _{SS})							
I I	Input Only Pin							
0	Output Only Pin							
I/O	Input/Output Pin							
S(E)	Synchronous, Edge Sensitive							
S(L)	Synchronous, Level Sensitive							
A(E)	Asynchronous, Edge Sensitive							
A(L)	Asynchronous, Level Sensitive							
H(1)	Output Driven to V _{CC} during Bus Hold							
H(0)	Output Driven to V _{SS} during Bus Hold							
H(Z)	Output Floats during Bus Hold							
H(Q)	Output Remains Active during Bus Hold							
H(X)	Output Retains Current State during Bus Hold							
R(WH)	Output Weakly Held at V _{CC} during Reset							
R(1)	Output Driven to V _{CC} during Reset							
R(0)	Output Driven to V _{SS} during Reset							
R(Z)	Output Floats during Reset							
R(Q)	Output Remains Active during Reset							
R(X)	Output Retains Current State during Reset							
l(1)	Output Driven to V _{CC} during Idle Mode							
I(0)	Output Driven to V _{SS} during Idle Mode							
I(Z)	Output Floats during Idle Mode							
I(Q)	Output Remains Active during Idle Mode							
I(X)	Output Retains Current State during Idle Mode							
P(1)	Output Driven to V _{CC} during Powerdown Mode							
P(0)	Output Driven to V _{SS} during Powerdown Mode							
P(Z)	Output Floats during Powerdown Mode							
P(Q)	Output Remains Active during Powerdown Mode							
P(X)	Output Retains Current State during Powerdown Mode							

Table 2. Pin Description Nomenclature

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Pin Name	Pin Type	Input Type	Output States	Description
Vcc	Р	_	—	POWER connections consist of four pins which must be shorted externally to a V_{CC} board plane.
V _{SS}	G	_	_	$\ensuremath{\textbf{GROUND}}$ connections consist of six pins which must be shorted externally to a V_{SS} board plane.
CLKIN	I	A(E)	_	CLock INput is an input for an external clock. An external oscillator operating at two times the required processor operating frequency can be connected to CLKIN. For crystal operation, CLKIN (along with OSCOUT) are the crystal connections to an internal Pierce oscillator.
OSCOUT	0		H(Q) R(Q) P(Q)	OSCillator OUTput is only used when using a crystal to generate the external clock. OSCOUT (along with CLKIN) are the crystal connections to an internal Pierce oscillator. This pin is not to be used as 2X clock output for non-crystal applications (i.e., this pin is N.C. for non-crystal applications). OSCOUT does not float in ONCE mode.
CLKOUT	0		H(Q) R(Q) P(Q)	CLocK OUTput provides a timing reference for inputs and outputs of the processor, and is one-half the input clock (CLKIN) frequency. CLKOUT has a 50% duty cycle and transistions every falling edge of CLKIN.
RESIN	I	A(L)	_	RESet IN causes the processor to immediately terminate any bus cycle in progress and assume an initialized state. All pins will be driven to a known state, and RESOUT will also be driven active. The rising edge (low-to-high) transition synchronizes CLKOUT with CLKIN before the processor begins fetching opcodes at memory location 0FFFF0H.
RESOUT	0	_	H(0) R(1) P(0)	RESet OUTput that indicates the processor is currently in the reset state. RESOUT will remain active as long as RESIN remains active.
PDTMR	1/0	A(L)	H(WH) R(Z) P(1)	Power-Down TiMeR pin (normally connected to an external capacitor) that determines the amount of time the processor waits after an exit from power down before resuming normal operation. The duration of time required will depend on the startup characteristics of the crystal oscillator.
NMI	I	A(E)	_	Non-Maskable Interrupt input causes a TYPE-2 interrupt to be serviced by the CPU. NMI is latched internally.
TEST/BUSY (TEST)	Ι	A(E)	_	TEST is used during the execution of the WAIT instruction to suspend CPU operation until the pin is sampled active (LOW). TEST is alternately known as BUSY when interfacing with an 80C187 numerics coprocessor (80C186EB only).
AD15:0 (AD7:0)	1/0	S(L)	H(Z) R(Z) P(X)	These pins provide a multiplexed Address and Data bus. During the address phase of the bus cycle, address bits 0 through 15 (0 through 7 on the 80C188EB) are presented on the bus and can be latched using ALE. 8- or 16-bit data information is transferred during the data phase of the bus cycle.

Table 3. Pin Descriptions

NOTE:

Pin names in parentheses apply to the 80C188EB/80L188EB.

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Table 3. Pin Descriptions (Continued)

Pin Name	Pin Type	Input Type	Output States				Description				
A18:16 A19/ONCE (A15:A8) (A18:16) (A19/ONCE)	1/0	A(L)	H(Z) R(WH) P(X)	These pins provide multiplexed Address during the address phase of the bus cycle. Address bits 16 through 19 are presented on these pins and can be latched using ALE. These pins are driven to a logic 0 during the data phase of the bus cycle. On the 80C188EB, A15–A8 provide valid address information for the entire bus cycle. During a processor reset (RESIN active), A19/ ONCE is used to enable ONCE mode. A18:16 must not be driven low during reset or improper operation may result.							
<u>S2:0</u>	0	_	H(Z) R(Z)				us are encoded on these pins to provide bus ormation. S2:0 are encoded as follows:				
			P(1)	<u>52</u>	<u>S1</u>	S0	Bus Cycle Initiated				
				0 0 0 1 1 1	0 1 1 0 1 1	0 1 0 1 0 1 0	Interrupt Acknowledge Read I/O Write I/O Processor HALT Queue Instruction Fetch Read Memory Write Memory Passive (no bus activity)				
ALE	0		H(0) R(0) P(0)	Address Latch Enable output is used to strobe address information into a transparent type latch during the address phase of the bus cycle.							
BHE (RFSH)	0	_	H(Z) R(Z) P(X)	is tra	ansfe	rring	able output to indicate that the bus cycle in progress data over the upper half of the data bus. BHE and llowing logical encoding				
				A0	Bl	ΗE	Encoding (for the 80C186EB/80L186EB only)				
				0 0 1 1) 1) 1	Word Transfer Even Byte Transfer Odd Byte Transfer Refresh Operation				
						C188 US Cyc	BEB/80L188EB, RFSH is asserted low to indicate a cle.				
RD	0	_	H(Z) R(Z) P(1)				ignals that the accessed memory or I/O device a information onto the data bus.				
WR	0		H(Z) R(Z) P(1)				signals that data available on the data bus are to be accessed memory or I/O device.				
READY	I	A(L) S(L)	_	READY input to signal the completion of a bus cycle. READY must be active to terminate any bus cycle, unless it is ignored by correctly programming the Chip-Select Unit.							
DEN	0	_	H(Z) R(Z) P(1)	tran	sceiv	ers in	output to control the enable of bi-directional a buffered system. DEN is active only when data is ed on the bus.				

NOTE:

Pin names in parentheses apply to the 80C188EB/80L188EB.

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Pin	Pin	Incut		
Name	Ріп Туре	Input Type	Output States	Description
DT/R	0	_	H(Z) R(Z) P(X)	Data Transmit/Receive output controls the direction of a bi-directional buffer in a buffered system. DT/\overline{R} is only available for the PLCC package.
LOCK	0	_	H(Z) R(WH) P(1)	LOCK output indicates that the bus cycle in progress is not to be interrupted. The processor will not service other bus requests (such as HOLD) while LOCK is active. This pin is configured as a weakly held high input while RESIN is active and must not be driven low.
HOLD	Ι	A(L)	_	HOLD request input to signal that an external bus master wishes to gain control of the local bus. The processor will relinquish control of the local bus between instruction boundaries not conditioned by a LOCK prefix.
HLDA	0	_	H(1) R(0) P(0)	HoLD Acknowledge output to indicate that the processor has relinquished control of the local bus. When HLDA is asserted, the processor will (or has) floated its data bus and control signals allowing another bus master to drive the signals directly.
NCS (N.C.)	0	_	H(1) R(1) P(1)	Numerics Coprocessor Select output is generated when accessing a numerics coprocessor. NCS is not provided on the QFP or SQFP packages. This signal does not exist on the 80C188EB/80L188EB.
ERROR (N.C.)	I	A(L)	_	ERROR input that indicates the last numerics coprocessor operation resulted in an exception condition. An interrupt TYPE 16 is generated if ERROR is sampled active at the beginning of a numerics operation. ERROR is not provided on the QFP or SQFP packages. This signal does not exist on the 80C188EB/80L188EB.
PEREQ (N.C.)	I	A(L)	_	CoProcessor REQuest signals that a data transfer between an External Numerics Coprocessor and Memory is pending. PEREQ is not provided on the QFP or SQFP packages. This signal does not exist on the 80C188EB/ 80L188EB.
UCS	0		H(1) R(1) P(1)	Upper Chip Select will go active whenever the address of a memory or I/O bus cycle is within the address limitations programmed by the user. After reset, UCS is configured to be active for memory accesses between 0FFC00H and 0FFFFFH.
LCS	0	—	H(1) R(1) P(1)	Lower Chip Select will go active whenever the address of a memory bus cycle is within the address limitations programmed by the user. LCS is inactive after a reset.
P1.0/GCS0 P1.1/GCS1 P1.2/GCS2 P1.3/GCS3 P1.4/GCS4 P1.5/GCS5 P1.6/GCS6 P1.7/GCS7	0	_	H(X)/H(1) R(1) P(X)/P(1)	These pins provide a multiplexed function. If enabled, each pin can provide a Generic Chip Select output which will go active whenever the address of a memory or I/O bus cycle is within the address limitations programmed by the user. When not programmed as a Chip-Select, each pin may be used as a general purpose output Port. As an output port pin, the value of the pin can be read internally.

Table 3. Pin Descriptions (Continued)

NOTE: Pin names in parentheses apply to the 80C188EB/80L188EB.

80C186EB/80C188EB, 80L186EB/80L188EB

Table 3. Pin Descriptions (Continued)										
Pin Name	Pin Type	Input Type	Output States	Description						
T0OUT T1OUT	0		H(Q) R(1) P(Q)	Timer OUTput pins can be programmed to provide a single clock or continuous waveform generation, depending on the timer mode selected.						
TOIN T1IN	I	A(L) A(E)	_	Timer INput is used either as clock or control signals, depending on the timer mode selected.						
INTO INT1 INT4	I	A(E,L)	_	Maskable INTerrupt input will cause a vector to a specific Type interrupt routine. To allow interrupt expansion, <u>INT0</u> and/or INT1 can be used with INTA0 and INTA1 to interface with an external slave controller.						
INT2/INTA0 INT3/INTA1	I/O	A(E,L)	H(1) R(Z) P(1)	These pins provide a multiplexed function. As inputs, they provide a maskable INTerrupt that will cause the CPU to vector to a specific Type interrupt routine. As outputs, each is programmatically controlled to provide an INTERRUPT ACKNOWLEDGE handshake signal to allow interrupt expansion.						
P2.7 P2.6	1/0	A(L)	H(X) R(Z) P(X)	BI-DIRECTIONAL, open-drain Port pins.						
CTSO P2.4/CTS1	I	A(L)	_	Clear-To-Send input is used to prevent the transmission of serial data on their respective TXD signal pin. CTS1 is multiplexed with an input only port function.						
TXD0 P2.1/TXD1	0	_	H(X)/H(Q) R(1) P(X)/P(Q)	Transmit Data output provides serial data information. TXD1 is multiplexed with an output only Port function. During synchronous serial communications, TXD will function as a clock output.						
RXD0 P2.0/RXD1	Ι/Ο	A(L)	R(Z) H(Q) P(X)	Receive Data input accepts serial data information. RXD1 is multiplexed with an input only Port function. During synchronous serial communications, RXD is bi-directional and will become an output for transmission or data (TXD becomes the clock).						
P2.5/BCLK0 P2.2/BCLK1	I	A(L)/A(E)	_	Baud CLocK input can be used as an alternate clock source for each of the integrated serial channels. BCLKx is multiplexed with an input only Port function, and cannot exceed a clock rate greater than one-half the operating frequency of the processor.						
P2.3/SINT1	0	_	H(X)/H(Q) R(0) P(X)/P(X)	Serial INTerrupt output will go active to indicate serial channel 1 requires service. SINT1 is multiplexed with an output only Port function.						

Table 3. Pin Descriptions (Continued)

NOTE:

Pin names in parentheses apply to the 80C188EB/80L188EB.



80C186EB PINOUT

Tables 4 and 5 list the 80C186EB/80C188EB pin names with package location for the 84-pin Plastic Leaded Chip Carrier (PLCC) component. Figure 5 depicts the complete 80C186EB/80C188EB pinout (PLCC package) as viewed from the top side of the component (i.e., contacts facing down). Tables 6 and 7 list the 80C186EB/80C188EB pin names with package location for the 80-pin Quad Flat Pack (QFP) component. Figure 6 depicts the complete 80C186EB/80C188EB (QFP package) as viewed from the top side of the component (i.e., contacts facing down).

Tables 8 and 9 list the 80186EB/80188EB pin names with package location for the 80-pin Shrink Quad Flat Pack (SQFP) component. Figure 7 depicts the complete 80C186EB/80C188EB (SQFP package) as viewed from the top side of the component (i.e., contacts facing down).

Address/I	Data Bus	Bus C	ontrol		Processor	Control	1/0	1/0	
Name	Location	Name	Location		Name	Location	Name	Location	
AD0	61	ALE	6		RESIN	37	UCS	30	
AD1	66	BHE (RFSH)	7		RESOUT	38	LCS	29	
AD2	68	SO	10		CLKIN	41	P1.0/GCS0	28	
AD3	70	S1	9		OSCOUT	40	P1.1/GCS1	27	
AD4	72	S2	8	1	CLKOUT	44	P1.2/GCS2	26	
AD5	74	RD	4		TEST/BUSY	14	P1.3/GCS3	25	
AD6	76	WR	5		NCS (N.C.)	60	P1.4/GCS4	24	
AD7	78	READY	18		PEREQ (N.C.)	39	P1.5/GCS5	21	
AD8 (A8)	62				ERROR (N.C.)	39	P1.6/GCS6	20	
AD9 (A9)	67	DEN	11		. ,	-	P1.7/GCS7	19	
AD10 (A10)	69	DT/R	16		PDTMR	36	TOOUT	45	
AD11 (A11)	71	LOCK	15	1	NMI	17	TOIN	46	
AD12 (A12)	73	HOLD	13		INT0	31	T1OUT	47	
AD13 (A13)	75	HLDA	12		INT1	32	T1IN	48	
AD14 (A14)	77				INT2/INTA0	33	RXD0	53	
AD15 (A15)	79	Po	ver]	INT3/INTA1	34	TXD0	52	
A16	80				INT4	35	P2.5/BCLK0		
A17	81	Name	Location					51	
A18	82	VSS	2, 22, 43				P2.0/RXD1	57	
A19/ONCE	83		63, 65, 84				P2.0/RXD1 P2.1/TXD1	57	
	,	V _{CC}	1,23				P2.1/TADT P2.2/BCLK1	59	
			42, 64				P2.3/SINT1	59	
			, • .	J			P2.3/SINT 1 P2.4/CTS1	56	
							P2.4/0151	00	

Table 4. PLCC Pin Names with Package Location

NOTE:

Pin names in parentheses apply to the 80C188EB/80L188EB.

P2.6

P2.7

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80C186EB/80C188EB, 80L186EB/80L188EB

Location	Name	Location	Name		Location	Name		Location	Name			
1	V _{CC}	22	V _{SS}		43	V _{SS}		64	V _{CC}			
2	V _{SS}	23	V _{CC}		44	CLKOUT		65	V _{SS}			
3	ERROR (N.C.)	24	P1.4/GCS4		45	TOOUT		66	AD1			
4	RD	25	P1.3/GCS3		46	TOIN		67	AD9 (A9)			
5	WR	26	P1.2/GCS2		47	T1OUT		68	AD2			
6	ALE	27	P1.1/GCS1		48	T1IN		69	AD10 (A10			
7	BHE (RFSH)	28	P1.0/GCS0		49	P2.7		70	AD3			
8	S2	29	LCS		50	P2.6		71	AD11 (A11			
9	S1	30	UCS		51	CTS0		72	AD4			
10	SO	31	INT0		52	TXD0		73	AD12 (A12			
11	DEN	32	INT1		53	RXD0		74	AD5			
12	HLDA	33	INT2/INTA0		54	P2.5/BCLK0		75	AD13 (A13			
13	HOLD	34	INT3/INTA1		55	P2.3/SINT1		76	AD6			
14	TEST/BUSY	35	INT4		56	P2.4/CTS1		77	AD14 (A14			
15	LOCK	36	PDTMR		57	P2.0/RXD1		78	AD7			
16	DT/R	37	RESIN		58	P2.1/TXD1		79	AD15 (A15			
17	NMI	38	RESOUT		59	P2.2/BCLK1		80	A16			
18	READY	39	PEREQ (N.C.)		60	NCS (N.C.)		81	A17			
19	P1.7/GCS7	40	OSCOUT		61	AD0		82	A18			
20	P1.6/GCS6	41	CLKIN		62	AD8 (A8)		83	A19/ONCE			
21	P1.5/GCS5	42	V _{CC}		63	V _{SS}		84	V _{SS}			

Table 5. PLCC Package Locations with Pin Name

NOTE: Pin names in parentheses apply to the 80C188EB/80L188EB.

80C186EB/80C188EB, 80L186EB/80L188EB

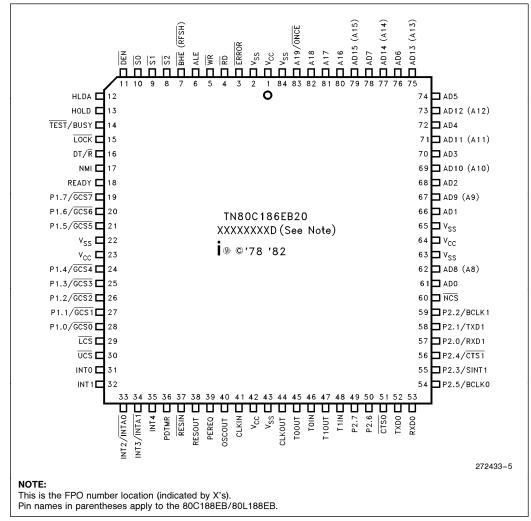


Figure 4. 84-Pin Plastic Leaded Chip Carrier Pinout Diagram

80C186EB/80C188EB, 80L186EB/80L188EB

P2.7

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		Table 6. Qr	P Pin Nam	e with Package	Location		
Address/Data Bus		Bus Co	Bus Control		Processor Control)
Name	Location	Name	Location	Name	Location	Name	Location
AD0	10	ALE	38	RESIN	68	UCS	61
AD1	15	BHE (RFSH)	39	RESOUT	69	LCS	60
AD2	17	SO	42	CLKIN	71	P1.0/GCS0	59
AD3	19	<u>S1</u>	41	OSCOUT	70	P1.1/GCS1	58
AD4	21	S2	40	CLKOUT	74	P1.2/GCS2	57
AD5	23	RD	36	TEST	46	P1.3/GCS3	56
AD6	25	WR	37	PDTMR	67	P1.4/GCS4	55
AD7	27	READY	49	NMI	48	P1.5/GCS5	52
AD8 (A8)	11		43	INT0	62	P1.6/GCS6	51
AD9 (A9)	16			INT1	63	P1.7/GCS7	50
AD10 (A10)	18	LOCK	47	INT2/INTA0	64	TOOUT	75
AD11 (A11)	20	HOLD	45	INT3/INTA1	65	TOIN	76
AD12 (A12)	22	HLDA	44	INT4	66	T1OUT	77
AD13 (A13)	24					T1IN	78
AD14 (A14)	26	Pow	er			RXD0	3
AD15 (A15)	28	Name	Location			TXD0	2
A16	29	Name	Location			P2.5/BCLK0	4
A17	30		12, 14, 33			CTS0	1
A18	31		35, 53, 73			P2.0/RXD1	7
A19/ONCE	32	V _{CC}	13, 34			P2.1/TXD1	8
			54, 72			P2.2/BCLK1	9
						P2.3/SINT1	5
						P2.4/CTS1	6
						P2.6	80

Table 6. QFP Pin Name with Package Location

NOTE: Pin names in parentheses apply to the 80C188EB/80L188EB.

80C186EB/80C188EB, 80L186EB/80L188EB

	Table 7: GFP Package Location with Pin Names								
Location	Name	Location	Name		Location	Name		Location	Name
1	CTS0	21	AD4		41	<u>S1</u>		61	UCS
2	TXD0	22	AD12 (A12)		42	SO		62	INT0
3	RXD0	23	AD5		43	DEN		63	INT1
4	P2.5/BCLK0	24	AD13 (A13)		44	HLDA		64	INT2/INTA0
5	P2.3/SINT1	25	AD6		45	HOLD		65	INT3/INTA1
6	P2.4/CTS1	26	AD14 (A14)		46	TEST		66	INT4
7	P2.0/RXD1	27	AD7		47	LOCK		67	PDTMR
8	P2.1/TXD1	28	AD15 (A15)		48	NMI		68	RESIN
9	P2.2/BCLK1	29	A16		49	READY		69	RESOUT
10	AD0	30	A17		50	P1.7/GCS7		70	OSCOUT
11	AD8 (A8)	31	A18		51	P1.6/GCS6		71	CLKIN
12	V _{SS}	32	A19/ONCE		52	P1.5/GCS5		72	V _{CC}
13	V _{CC}	33	V _{SS}		53	V _{SS}		73	V _{SS}
14	V _{SS}	34	V _{CC}		54	V _{CC}		74	CLKOUT
15	AD1	35	V _{SS}		55	P1.4/GCS4		75	TOOUT
16	AD9 (A9)	36	RD		56	P1.3/GCS3		76	TOIN
17	AD2	37	WR		57	P1.2/GCS2		77	T1OUT
18	AD10 (A10)	38	ALE		58	P1.1/GCS1		78	T1IN
19	AD3	39	BHE (RFSH)		59	P1.0/GCS0		79	P2.7
20	AD11 (A11)	40	S2		60	LCS		80	P2.6

Table 7. QFP Package Location with Pin Names

NOTE:

Pin names in parentheses apply to the 80C188EB/80L188EB.

80C186EB/80C188EB, 80L186EB/80L188EB

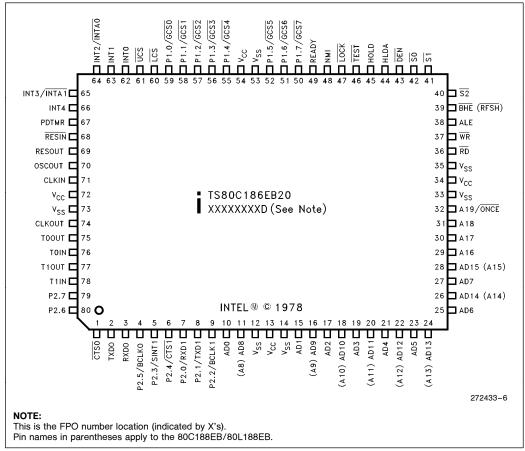


Figure 5. Quad Flat Pack Pinout Diagram

80C186EB/80C188EB, 80L186EB/80L188EB

AD Bus				
AD0	47			
AD1	52			
AD2	54			
AD3	56			
AD4	58			
AD5	60			
AD6	62			
AD7	64			
AD8 (A8)	48			
AD9 (A9)	53			
AD10 (A10)	55			
AD11 (A11)	57			
AD12 (A12)	59			
AD13 (A13)	61			
AD14 (A14)	63			
AD15 (A15)	65			
A16	66			
A17	67			
A18	68			
A19/ONCE	69			

Table 8. SQFP Pin Functions with						
Bus Control			Process			
ALE BHE # (RFSH #) S0 # S1 # S2 # RD # WR # READY DEN #	75 76 79 78 77 73 74 6 80		RESIN# RESOUT CLKIN OSCOUT CLKOUT TEST#/B NMI INT0 INT1			
LOCK# HOLD HLDA	4 2 1		INT2/INTA INT3/INTA INT4 PDTMR			
			Power a			

ctions with Location	n	
Processor Contr	I/O	
RESIN#	25	UCS#
RESOUT	26	LCS#
CLKIN	28	
OSCOUT	27	P1.0/GCS0#
CLKOUT	31	P1.1/GCS1#
TEST#/BUSY	3	P1.2/GCS2#
NMI	5	P1.3/GCS3#
INT0	19	P1.4/GCS4#
INT1	20	P1.5/GCS5#
INT2/INTA0#	21	P1.6/GCS6#
INT3/INTA1#	22	P1.7/GCS7#
INT4	23	
PDTMR	24	P2.0/RXD1
		P2.1/TXD1
Power and Grou	nd	P2.2/BCLK1
		P2.3/SINT1
V _{CC}	11	P2.4/CTS1#
V _{CC}	29	P2.5/BCLK0
V _{CC}	50	P2.6
V _{CC}	71	P2.7
V _{SS}	10	
V _{SS}	30	CTS0#
V _{SS}	49	TXD0
V _{SS}	51	RXD0
V _{SS}	70	
V _{SS} V _{SS}	70 72	TOIN
		T1IN

Table 9. SQFP Pin Locations with Pin Names

			,		_			
1	HLDA	21	INT1/INTA0#	41		P2.5/BCLK0	61	AD13 (A13)
2	HOLD	22	INT3/INTA1#	42	2	P2.3/SINT1	62	AD6
3	TEST#	23	INT4	43	3	P2.4/CTS1#	63	AD14 (A14)
4	LOCK#	24	PDTMR	44	1	P2.0/RXD1	64	AD7
5	NMI	25	RESIN#	45	5	P2.1/TXD1	65	AD15 (A15)
6	READY	26	RESOUT	46	3	P2.2/BCLK1	66	A16
7	P1.7/GCS7#	27	OSCOUT	47	7	AD0	67	A17
8	P1.6/GCS6#	28	CLKIN	48	3	AD8 (A8)	68	A18
9	P1.5/GCS5#	29	V _{CC}	49)	V _{SS}	69	A19/ONCE
10	V _{SS}	30	V _{SS}	50)	V _{CC}	70	V _{SS}
11	V _{CC}	31	CLKOUT	51	I	V _{SS}	71	V _{CC}
12	P1.4/GCS4#	32	TOOUT	52	2	AD1	72	V _{SS}
13	P1.3/GCS3#	33	TOIN	53	3	AD9 (A9)	73	RD#
14	P1.2/GCS2#	34	T1OUT	54	1	AD2	74	WR#
15	P1.1/GCS1#	35	T1IN	55	5	AD10 (A10)	75	ALE
16	P1.0/GCS0#	36	P2.7	56	3	AD3	76	BHE# (RFSH#)
17	LCS#	37	P2.6	57	7	AD11 (A11)	77	S2#
18	UCS#	38	CTS0#	58	3	AD4	78	S1#
19	INT0	39	TXD0	59)	AD12 (A12)	79	S0#
20	INT1	40	RXD0	60)	AD5	80	DEN#

NOTE:

Pin names in parentheses apply to the 80C188EB/80L188EB.

80C186EB/80C188EB, 80L186EB/80L188EB

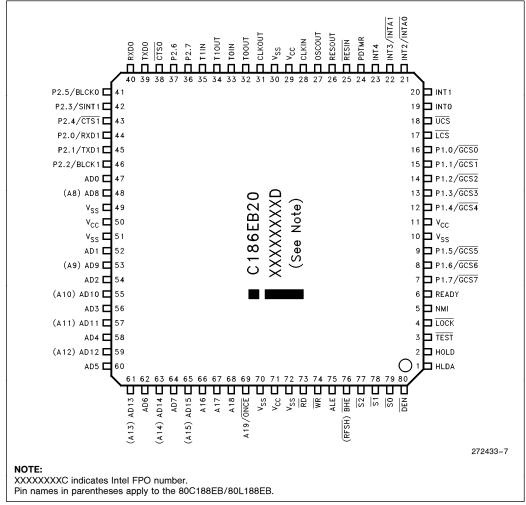


Figure 6. SQFP Package

PRELIMINARY



PACKAGE THERMAL SPECIFICATIONS

The 80C186EB/80L186EB is specified for operation when T_C (the case temperature) is within the range of -40° C to $+100^\circ$ C (PLCC package) or -40° C to $+114^\circ$ C (QFP package). T_C may be measured in any environment to determine whether the processor is within the specified operating range. The case temperature must be measured at the center of the top surface.

 T_A (the ambient temperature) can be calculated from θ_{CA} (thermal resistance from the case to ambient) with the following equation:

$$\mathsf{T}_{\mathsf{A}} = \mathsf{T}_{\mathsf{C}} - \mathsf{P}^* \theta_{\mathsf{C}}$$

Typical values for θ_{CA} at various airflows are given in Table 10. P (the maximum power consumption, specified in watts) is calculated by using the maximum ICC as tabulated in the DC specifications and V_{CC} of 5.5V.

Table 10. Thermal Resistance (θ_{CA}) at Various Airflows (in °C/Watt)

	Airflow Linear ft/min (m/sec)							
	0 (0)	200 (1.01)	400 (2.03)	600 (3.04)	800 (4.06)	1000 (5.07)		
θ_{CA} (PLCC)	30	24	21	19	17	16.5		
θ_{CA} (QFP)	58	47	43	40	38	36		
θ_{CA} (SQFP)	70	TBD	TBD	TBD	TBD	TBD		

80C186EB/80C188EB, 80L186EB/80L188EB

ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings

Storage Temperature $\dots -65^{\circ}C$ to $+150^{\circ}C$
Case Temp under Bias $\dots -65^{\circ}C$ to $+120^{\circ}C$
Supply Voltage with Respect to V_{SS} $\ldots \ldots -0.5 V$ to $+~6.5 V$
Voltage on other Pins with Respect to V_{SS} $\ldots \ldots -0.5V$ to V_{CC} + 0.5V

Recommended Connections

Power and ground connections must be made to multiple V_{CC} and V_{SS} pins. Every 80C186EB-based circuit board should include separate power (V_{CC}) and ground (V_{SS}) planes. Every V_{CC} pin must be connected to the power plane, and every V_{SS} pin must be connected to the ground plane. Pins identified as "NC" must not be connected in the system. Liberal decoupling capacitance should be placed near the processor. The processor can cause transient power surges when its output buffers transition, particularly when connected to large capacitive loads.

NOTICE: This data sheet contains preliminary information on new products in production. It is valid for the devices indicated in the revision history. The specifications are subject to change without notice.

*WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

Low inductance capacitors and interconnects are recommended for best high frequency electrical performance. Inductance is reduced by placing the decoupling capacitors as close as possible to the processor V_{CC} and V_{SS} package pins.

Always connect any unused input to an appropriate signal level. In particular, unused interrupt inputs (INT0:4) should be connected to V_{CC} through a pullup resistor (in the range of 50 K Ω). Leave any unused output pin or any NC pin unconnected.



DC SPECIFICATIONS (80C186EB/80C188EB)

Symbol	Parameter	Min	Max	Units	Notes
V _{CC}	Supply Voltage	4.5	5.5	V	
VIL	Input Low Voltage	-0.5	0.3 V _{CC}	V	
V _{IH}	Input High Voltage	0.7 V _{CC}	$V_{CC} + 0.5$	V	
V _{OL}	Output Low Voltage		0.45	V	I _{OL} = 3 mA (Min)
V _{OH}	Output High Voltage	V _{CC} - 0.5		V	$I_{OH} = -2 \text{ mA} (MIn)$
V _{HYR}	Input Hysterisis on RESIN	0.50		V	
I _{LI1}	Input Leakage Current for Pins: AD15:0 (AD7:0), READY, HOLD, RESIN, CLKIN, TEST, NMI, INT4:0, TOIN, T1IN, RXD0, BCLK0, CTS0, RXD1, BCLK1, CTS1, P2.6, P2.7		±15	μΑ	$0V \leq V_{IN} \leq V_{CC}$
I _{LI2}	Input Leakage Current for Pins: ERROR, PEREQ	±0.275	±7	mA	$\text{ov} \leq \text{v}_{\text{IN}} < \text{v}_{\text{CC}}$
I _{LI3}	Input Leakage Current for Pins: A19/ONCE, A18:16, LOCK	-0.275	-5.0	mA	$V_{IN} = 0.7 V_{CC}$ (Note 1)
I _{LO}	Output Leakage Current		±15	μΑ	0.45 \leq V _{OUT} \leq V _{CC} (Note 2)
ICC	Supply Current Cold (RESET) 80C186EB25		115	mA	(Notes 3, 7)
	80C186EB20		108	mA	(Note 3)
	80C186EB13		73	mA	(Note 3)
I _{ID}	Supply Current Idle 80C186EB25		91	mA	(Notes 4, 7)
	80C186EB20		76	mA	(Note 4)
	80C186EB13		48	mA	(Note 4)
I _{PD}	Supply Current Powerdown 80C186EB25		100	μΑ	(Notes 5, 7)
	80C186EB20		100	μΑ	(Note 5)
	80C186EB13		100	μΑ	(Note 5)
C _{IN}	Input Pin Capacitance	0	15	pF	$T_{F} = 1 MHz$
C _{OUT}	Output Pin Capacitance	0	15	pF	T _F = 1 MHz (Note 6)

NOTES:

1. These pins have an internal pull-up device that is active while RESIN is low and ONCE Mode is not active. Sourcing more

1. These pins have an internal pull-up device that is active while HSIN is low and ONCE Mode is not active. Sourcing more current than specified (on any of these pins) may invoke a factory test mode. 2. Tested by outputs being floated by invoking ONCE Mode or by asserting HOLD. 3. Measured with the device in RESET and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND. 4. Measured with the device in HALT (IDLE Mode active) and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND. 5. Measured with the device in HALT (IDLE Mode active) and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

5. Measured with the device in HALT (Powerdown Mode active) and at worst case frequency, V_{CC}, and temperature with ALL outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

6. Output Capacitance is the capacitive load of a floating output pin.

7. Operating temperature for 25 MHz is 0°C to 70°C, V_{CC} = 5.0 \pm 10%.

80C186EB/80C188EB, 80L186EB/80L188EB

Symbol	Parameter	Min	Max	Units	Notes
V _{CC}	Supply Voltage	3.0	5.5	V	
VIL	Input Low Voltage	-0.5	0.3 V _{CC}	V	
V _{IH}	Input High Voltage	0.7 V _{CC}	$V_{CC} + 0.5$	V	
V _{OL}	Output Low Voltage		0.45	V	$I_{OL} = 1.6 \text{ mA}$ (Min) (Note 1)
V _{OH}	Output High Voltage	$V_{CC} - 0.5$		V	$I_{OH} = -1 \text{ mA}$ (Min) (Note 1)
V _{HYR}	Input Hysterisis on RESIN	0.50		V	
I _{LI1}	Input Leakage Current for pins: AD15:0 (AD7:0), READY, HOLD, RESIN, CLKIN, TEST, NMI, INT4:0, TOIN, T1IN, RXD0, BCLK0, CTS0, RXD1, BCLK1, CTS1, SINT1, P2.6, P2.7		±15	μΑ	$0V \leq V_{IN} \leq V_{CC}$
I _{LI2}	Input Leakage Current for Pins: A19/ONCE, A18:16, LOCK	-0.275	-2	mA	$V_{IN} = 0.7 V_{CC}$ (Note 2)
ILO	Output Leakage Current		±15	μΑ	$0.45 \leq V_{OUT} \leq V_{CC}$ (Note 3)
I _{CC3}	Supply Current (RESET, 3.3V) 80L186EB16		54	mA	(Note 4)
I _{ID3}	Supply Current Idle (3.3V) 80L186EB16		38	mA	(Note 5)
I _{PD3}	Supply Current Powerdown (3.3V) 80L186EB16		40	μΑ	(Note 6)
C _{IN}	Input Pin Capacitance	0	15	pF	$T_F = 1 MHz$
C _{OUT}	Output Pin Capacitance	0	15	pF	T _F = 1 MHz (Note 7)

DC SPECIFICATIONS (80L186EB16) (operating temperature, 0°C to 70°C)

NOTES:

1. I_{OL} and I_{OH} measured at $V_{CC}\,=\,3.0V.$

2. These pins have an internal pull-up device that is active while RESIN is low and ONCE Mode is not active. Sourcing more current than specified (on any of these pins) may invoke a factory test mode.

3. Tested by outputs being floated by invoking ONCE Mode or by asserting HOLD. 4. Measured with the device in RESET and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

5. Measured with the device in HALT (IDLE Mode active) and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

ALL outputs loaded as specified in AC Test Conditions, and all floating outputs driver to V_{CC} or GND.

7. Output Capacitance is the capacitive load of a floating output pin.



Symbol	Parameter	Min	Max	Units	Notes
V _{CC}	Supply Voltage	2.7	5.5	V	
V _{IL}	Input Low Voltage	-0.5	0.3 V _{CC}	V	
VIH	Input High Voltage	0.7 V _{CC}	V _{CC} + 0.5	V	
V _{OL}	Output Low Voltage		0.45	V	I _{OL} = 1.6 mA (Min) (Note 1)
V _{OH}	Output High Voltage	$V_{CC} - 0.5$		V	$I_{OH} = -1 \text{ mA}$ (Min) (Note 1)
V _{HYR}	Input Hysterisis on RESIN	0.50		V	
I _{LI1}	Input Leakage Current for pins: AD15:0 (AD7:0), READY, HOLD, RESIN, CLKIN, TEST, NMI, INT4:0, TOIN, T1IN, RXD0, BCLK0, CTS0, RXD1, BCLK1, CTS1, SINT1, P2.6, P2.7		± 15	μΑ	$0V \le V_{IN} \le V_{CC}$
I _{LI2}	Input Leakage Current for Pins: A19/ONCE, A18:16, LOCK	-0.275	-2	mA	$V_{IN} = 0.7 V_{CC}$ (Note 2)
I _{LO}	Output Leakage Current		±15	μΑ	$0.45 \leq V_{OUT} \leq V_{CC}$ (Note 3)
I _{CC5}	Supply Current (RESET, 5.5V) 80L186EB13 80L186EB8		73 45	mA mA	(Note 4) (Note 4)
I _{CC3}	Supply Current (RESET, 2.7V) 80L186EB13 80L186EB8		36 22	mA mA	(Note 4) (Note 4)
I _{ID5}	Supply Current Idle (5.5V) 80L186EB13 80L186EB8		48 31	mA mA	(Note 5) (Note 5)
I _{ID3}	Supply Current Idle (2.7V) 80L186EB13 80L186EB8		24 15	mA mA	(Note 5) (Note 5)
I _{PD5}	Supply Current Powerdown (5.5V) 80L186EB13 80L186EB8		100 100	μΑ μΑ	(Note 6) (Note 6)
I _{PD3}	Supply Current Powerdown (2.7V) 80L186EB13 80L186EB8		30 30	μΑ μΑ	(Note 6) (Note 6)
C _{IN}	Input Pin Capacitance	0	15	pF	$T_F = 1 MHz$
C _{OUT}	Output Pin Capacitance	0	15	pF	T _F = 1 MHz (Note 7)

DC SPECIFICATIONS (80L186EB13/80L188EB13, 80L186EB8/80L188EB8)

NOTES:

NOTES: 1. $|_{OL}$ and $|_{OH}$ measured at $V_{CC} = 2.7V$. 2. These pins have an internal pull-up device that is active while RESIN is low and ONCE Mode is not active. Sourcing more current than specified (on any of these pins) may invoke a factory test mode. 3. Tested by outputs being floated by invoking ONCE Mode or by asserting HOLD. 4. Measured with the device in RESET and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND. 5. Measured with the device in HALT (IDLE Mode active) and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND. 6. Measured with the device in HALT (Powerdown Mode active) and at worst case frequency, V_{CC} , and temperature with **ALL** outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND. 7. Outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or GND.

7. Output Capacitance is the capacitive load of a floating output pin.

Intal

ICC VERSUS FREQUENCY AND VOLTAGE

The current (I_{CC}) consumption of the processor is essentially composed of two components; IPD and ICCS.

IPD is the quiescent current that represents internal device leakage, and is measured with all inputs or floating outputs at GND or V_{CC} (no clock applied to the device). $I_{\mbox{PD}}$ is equal to the Powerdown current and is typically less than 50 μ A.

 I_{CCS} is the switching current used to charge and discharge parasitic device capacitance when changing logic levels. Since I_{CCS} is typically much greater than IPD, IPD can often be ignored when calculating Icc.

 I_{CCS} is related to the voltage and frequency at which the device is operating. It is given by the formula:

Power = V
$$\times$$
 I = V² \times C_{DEV} \times 1

 $\therefore I = I_{CC} = I_{CCS} = V \times C_{DEV} \times f$

Where: V = Device operating voltage (V_{CC})

C_{DEV} = Device capacitance

f = Device operating frequency

 $I_{CCS} = I_{CC} = Device current$

Measuring C_{DEV} on a device like the 80C186EB would be difficult. Instead, CDEV is calculated using the above formula by measuring I_{CC} at a known V_{CC} and frequency (see Table 11). Using this CDEV value, I_{CC} can be calculated at any voltage and frequency within the specified operating range.

EXAMPLE: Calculate the typical $I_{\mbox{CC}}$ when operating at 10 MHz, 4.8V.

$$I_{\rm CC} = I_{\rm CCS} = 4.8 \times 0.583 \times 10 \approx 28$$
 mA

80C186EB/80C188EB, 80L186EB/80L188EB

PDTMR PIN DELAY CALCULATION

The PDTMR pin provides a delay between the assertion of NMI and the enabling of the internal clocks when exiting Powerdown. A delay is required only when using the on-chip oscillator to allow the crystal or resonator circuit time to stabilize.

NOTE:

The PDTMR pin function does not apply when RESIN is asserted (i.e., a device reset during Powerdown is similar to a cold reset and RESIN must remain active until after the oscillator has stabilized).

To calculate the value of capacitor required to provide a desired delay, use the equation:

440
$$\times$$
 t = C_{PD} (5V, 25°C)

Where: t = desired delay in seconds

EXAMPLE: To get a delay of 300 µs, a capacitor value of $C_{PD} = 440 \times (300 \times 10^{-6}) = 0.132 \,\mu\text{F}$ is required. Round up to standard (available) capacitive values.

NOTE:

The above equation applies to delay times greater than 10 µs and will compute the TYPICAL capacitance needed to achieve the desired delay. A delay variance of +50% or -25% can occur due to temperature, voltage, and device process extremes. In general, higher V_{CC} and/or lower temperature will decrease delay time, while lower V_{CC} and/or higher temperature will increase delay time.

Table 11. Device Capacitance	(C _{DEV}) Values
------------------------------	----------------------------

Parameter	Тур	Max	Units	Notes
C _{DEV} (Device in Reset)	0.583	1.02	mA/V*MHz	1, 2
C _{DEV} (Device in Idle)	0.408	0.682	mA/V*MHz	1, 2

1. Max C_{DEV} is calculated at $-40^\circ\text{C},$ all floating outputs driven to V_{CC} or GND, and all outputs loaded to 50 pF (including CLKOUT and OSCOUT). 2. Typical C_{DEV} is calculated at 25°C with all outputs loaded to 50 pF except CLKOUT and

OSCOUT, which are not loaded.



AC SPECIFICATIONS

AC Characteristics—80C186EB25

Symbol	Parameter	25	MHz	Units	Notes
Symbol	Parameter	Min	Max	Units	Notes
INPUT C	LOCK				
T _F	CLKIN Frequency	0	50	MHz	1
T _C	CLKIN Period	20	×	ns	1
T _{CH}	CLKIN High Time	8	×	ns	1, 2
T _{CL}	CLKIN Low Time	8	×	ns	1, 2
T _{CR}	CLKIN Rise Time	1	7	ns	1, 3
T _{CF}	CLKIN Fall Time	1	7	ns	1, 3
OUTPUT	CLOCK				
T _{CD}	CLKIN to CLKOUT Delay	0	16	ns	1, 4
Т	CLKOUT Period		2*T _C	ns	1
T _{PH}	CLKOUT High Time	(T/2) — 5		ns	1
T _{PL}	CLKOUT Low Time	(T/2) - 5	(T/2) + 5	ns	1
T _{PR}	CLKOUT Rise Time	1	6	ns	1, 5
T _{PF}	CLKOUT Fall Time	1	6	ns	1, 5
OUTPUT	DELAYS				
T _{CHOV1}	ALE, $\overline{S2:0}$, \overline{DEN} , DT/\overline{R} , \overline{BHE} (\overline{RFSH}), \overline{LOCK} , A19:16	3	17	ns	1, 4, 6, 7
T _{CHOV2}	GCS0:7, LCS, UCS, NCS, RD, WR	3	20	ns	1, 4, 6, 8
T _{CLOV1}	BHE (RFSH), DEN, LOCK, RESOUT, HLDA, TOOUT, T1OUT, A19:16	3	17	ns	1, 4, 6
T _{CLOV2}	RD, WR, GCS7:0, LCS, UCS, AD15:0 (AD7:0, A15:8), NCS, INTA1:0, S2:0	3	20	ns	1, 4, 6
T _{CHOF}	RD, WR, BHE (RFSH), DT/R, LOCK, S2:0, A19:16	0	20	ns	1
T _{CLOF}	DEN, AD15:0 (AD7:0, A15:8)	0	20	ns	1

AC SPECIFICATIONS

AC Characteristics—80C186EB25 (Continued)

Symbol Parameter	Parameter		25 MHz		Notes			
	Farameter	Min	Max	Units	NOLES			
SYNCHR	SYNCHRONOUS INPUTS							
T _{CHIS}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0, P2.6, P2.7	10		ns	1, 9			
T _{CHIH}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0	3		ns	1, 9			
T _{CLIS}	AD15:0 (AD7:0), READY	10		ns	1, 10			
T _{CLIH}	READY, AD15:0 (AD7:0)	3		ns	1, 10			
T _{CLIS}	HOLD, PEREQ, ERROR	10		ns	1, 9			
T _{CLIH}	HOLD, PEREQ, ERROR	3		ns	1, 9			

NOTES:

NOTES: 1. See **AC Timing Waveforms**, for waveforms and definition. 2. Measure at V_{IH} for high time, V_{IL} for low time. 3. Only required to guarantee I_{CC}. Maximum limits are bounded by T_C, T_{CH} and T_{CL}. 4. Specified for a 50 pF load, see Figure 13 for capacitive derating information. 5. Specified for a 50 pF load, see Figure 14 for rise and fall times outside 50 pF. 6. See Figure 14 for rise and fall times. 7. T_{CHOV1} applies to BHE (RFSH), LOCK and A19:16 only after a HOLD release. 8. T_{CHOV2} applies to RD and WR only after a HOLD release. 9. Setup and Hold are required to guarantee recognition. 10. Setup and Hold are required for proper operation.



AC SPECIFICATIONS

AC Characteristics—80C186EB20/80C186EB13

Symbol	Parameter	20	MHz	13	MHz	Units	Notes
	Farameter	Min	Max	Min	Max	Units	Notes
INPUT C	LOCK						
T _F	CLKIN Frequency	0	40	0	26	MHz	1
T _C	CLKIN Period	25	~	38.5	∞	ns	1
т _{сн}	CLKIN High Time	10	~	12	œ	ns	1, 2
T _{CL}	CLKIN Low Time	10	~	12	~	ns	1, 2
T _{CR}	CLKIN Rise Time	1	8	1	8	ns	1, 3
T _{CF}	CLKIN Fall Time	1	8	1	8	ns	1, 3
OUTPUT	CLOCK						
T _{CD}	CLKIN to CLKOUT Delay	0	17	0	23	ns	1, 4
Т	CLKOUT Period		2*T _C		2*T _C	ns	1
Т _{РН}	CLKOUT High Time	(T/2) - 5	(T/2) + 5	(T/2) - 5	(T/2) + 5	ns	1
T _{PL}	CLKOUT Low Time	(T/2) - 5	(T/2) + 5	(T/2) — 5	(T/2) + 5	ns	1
T _{PR}	CLKOUT Rise Time	1	6	1	6	ns	1, 5
T _{PF}	CLKOUT Fall Time	1	6	1	6	ns	1, 5
OUTPUT	DELAYS						
T _{CHOV1}	ALE, <u>S2:0, DEN, DT/R,</u> BHE (RFSH), LOCK, A19:16	3	22	3	25	ns	1, 4, 6, 7
T _{CHOV2}	GCS0:7, LCS, UCS, NCS, RD, WR	3	27	3	30	ns	1, 4, 6, 8
T _{CLOV1}	BHE (RFSH), DEN, LOCK, RESOUT, HLDA, TOOUT, T1OUT, A19:16	3	22	3	25	ns	1, 4, 6
T _{CLOV2}	RD, WR, GCS7:0, LCS, UCS, AD15:0 (AD7:0, A15:8), NCS, INTA1:0, S2:0	3	27	3	30	ns	1, 4, 6
T _{CHOF}	RD, WR, BHE (RFSH), DT/R, LOCK, S2:0, A19:16	0	25	0	25	ns	1
T _{CLOF}	DEN, AD15:0 (AD7:0, A15:8)	0	25	0	25	ns	1

AC SPECIFICATIONS

Symbol	Parameter	20 MHz		13	MHz	Units	Notes	
Symbol	Parameter		Max	Min	Мах	Units	Notes	
SYNCHRONOUS INPUTS								
T _{CHIS}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0, P2.6, P2.7	10		10		ns	1, 9	
Т _{СНІН}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0	3		3		ns	1, 9	
T _{CLIS}	AD15:0 (AD7:0), READY	10		10		ns	1, 10	
T _{CLIH}	READY, AD15:0 (AD7:0)	3		3		ns	1, 10	
T _{CLIS}	HOLD, PEREQ, ERROR	10		10		ns	1, 9	
T _{CLIH}	HOLD, PEREQ, ERROR	3		3		ns	1, 9	

AC Characteristics—80C186EB20/80C186EB13 (Continued)

NOTES:

1. See AC Timing Waveforms, for waveforms and definition.

- 1. See **AC Timing Waveforms**, for waveforms and definition. 2. Measure at V_{IH} for high time, V_{IL} for low time. 3. Only required to guarantee I_{CC}. Maximum limits are bounded by T_C, T_{CH} and T_{CL}. 4. Specified for a 50 pF load, see Figure 13 for capacitive derating information. 5. Specified for a 50 pF load, see Figure 14 for rise and fall times outside 50 pF. 6. See Figure 14 for rise and fall times. 7. T_{CHOV1} applies to BHE (RFSH), LOCK and A19:16 only after a HOLD release. 8. T_{CHOV2} applies to RD and WR only after a HOLD release. 9. Setup and Hold are required to guarantee recognition. 10. Setup and Hold are required for proper operation.



AC SPECIFICATIONS

AC Characteristics—80L186EB16

Symbol	Devementer	16	MHz	Units	Notes
Symbol	Parameter	Min	Max	Units	Notes
INPUT C	LOCK				
T _F	CLKIN Frequency	0	32	MHz	1
TC	CLKIN Period	31.25	æ	ns	1
Т _{СН}	CLKIN High Time	13	~	ns	1, 2
T _{CL}	CLKIN Low Time	13	~	ns	1, 2
T _{CR}	CLKIN Rise Time	1	8	ns	1, 3
T _{CF}	CLKIN Fall Time	1	8	ns	1, 3
OUTPUT	CLOCK				
T _{CD}	CLKIN to CLKOUT Delay	0	30	ns	1, 4
Т	CLKOUT Period		2*T _C	ns	1
T _{PH}	CLKOUT High Time	(T/2) - 5	(T/2) + 5	ns	1
T _{PL}	CLKOUT Low Time	(T/2) - 5	(T/2) + 5	ns	1
T _{PR}	CLKOUT Rise Time	1	9	ns	1, 5
T _{PF}	CLKOUT Fall Time	1	9	ns	1, 5
OUTPUT	DELAYS				
T _{CHOV1}	DT/R, LOCK, A19:16, R _{FSH}	3	22	ns	1, 4, 6, 7
T _{CHOV2}	GCS0:7, LCS, UCS, NCS, RD, WR	3	27	ns	1, 4, 6, 8
T _{CHOV3}	BHE, DEN	3	25	ns	1, 4
T _{CHOV4}	ALE	3	30	ns	1, 4
T _{CHOV5}	<u>S2:0</u>	3	33	ns	1, 4
T _{CLOV1}	LOCK, RESOUT, HLDA, TOOUT, T1OUT, A19:16	3	22	ns	1, 4, 6
T _{CLOV2}	RD, WR, GCS7:0, LCS, UCS, NCS, INTA1:0, AD15:0 (AD7:0, A15:8)	3	27	ns	1, 4, 6
T _{CHOF}	RD, WR, BHE (RFSH), DT/R, LOCK, S2:0, A19:16	0	25	ns	1
T _{CLOF}	DEN, AD15:0 (AD7:0, A15:8)	0	25	ns	1
T _{CLOV3}	BHE, DEN	3	25	ns	1, 4, 6
T _{CLOV5}	<u>\$2:0</u>	3	33	ns	1, 4, 6

AC SPECIFICATIONS

AC Characteristics—80L186EB16 (Continued)

Symbol	Parameter		16 MHz		Notes		
			Max	Units	Notes		
SYNCHR	SYNCHRONOUS INPUTS						
T _{CHIS}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0, P2.6, P2.7	15		ns	1, 9		
T _{CHIH}	TEST, NMI, INT4:0, T1:0IN, BCLK1:0, READY, CTS1:0	3		ns	1, 9		
T _{CLIS}	AD15:0 (AD7:0), READY	15		ns	1, 10		
T _{CLIH}	READY, AD15:0 (AD7:0)	3		ns	1, 10		
T _{CLIS}	HOLD	15		ns	1, 9		
T _{CLIH}	HOLD	3		ns	1, 9		

NOTES:

NOTES: 1. See **AC Timing Waveforms**, for waveforms and definition. 2. Measure at V_{IH} for high time, V_{IL} for low time. 3. Only required to guarantee I_{CC}. Maximum limits are bounded by T_C, T_{CH} and T_{CL}. 4. Specified for a 50 pF load, see Figure 13 for capacitive derating information. 5. Specified for a 50 pF load, see Figure 14 for rise and fall times outside 50 pF. 6. See Figure 14 for rise and fall times. 7. T_{CHOV1} applies to BHE (RFSH), LOCK and A19:16 only after a HOLD release. 8. T_{CHOV2} applies to RD and WR only after a HOLD release. 9. Setup and Hold are required to guarantee recognition. 10. Setup and Hold are required for proper operation.



AC SPECIFICATIONS

AC Characteristics—80L186EB13/80L186EB8

Symbol	Parameter	13	MHz	8 N	lHz	Units	Notes
Symbol	Falameter	Min	Max	Min	Max	Onits	Notes
INPUT CI	LOCK						
Tr	CLKIN Frequency	0	26	0	16	MHz	1
TC	CLKIN Period	38.5	~	62.5	∞	ns	1
TCH	CLKIN High Time	15	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~	15	8	ns	1, 2
T _{CL}	CLKIN Low Time	15	~	15	~	ns	1, 2
T _{CR}	CLKIN Rise Time	1	8	1	8	ns	1,3
T _{CF}	CLKIN Fall Time	1	8	1	8	ns	1, 3
OUTPUT			1			1	
T _{CD}	CLKIN to CLKOUT Delay	0	10	0	50	ns	1, 4
Т	CLKOUT Period		2*T _C		2*T _C	ns	1
T _{PH}	CLKOUT High Time	(T/2) — 5	(T/2) +5	(T/2) — 5	(T/2) +5	ns	1
T _{PL}	CLKOUT Low Time	(T/2) — 5	(T/2) + 5	(T/2) — 5	(T/2) + 5	ns	1
T _{PR}	CLKOUT Rise Time	1	10	1	15	ns	1, 5
T _{PF}	CLKOUT Fall Time	1	10	1	15	ns	1, 5
OUTPUT	DELAYS						
T _{CHOV1}	ALE, S2-0, DEN, DT/R, BHE (RFSH), LOCK, A19:16	3	25	3	30	ns	1, 4, 6, 7
T _{CHOV2}	GCS0:7, LCS, UCS, NCS, RD, WR	3	30	3	35	ns	1, 4,6, 8
T _{CLOV1}	BHE (RFSH), DEN, LOCK, RESOUT, HLDA, T0OUT, T1OUT, A19:16	3	25	3	30	ns	1, 4, 6
T _{CLOV2}	S2:0, RD, WR, GCS7:0, LCS, UCS, NCS, INTA1:0, AD15:0 (AD7:0, A15:8)	3	30	3	35	ns	1, 4, 6
T _{CHOF}	RD, WR, BHE (RFSH), DT/R, LOCK, S2:0, A19:16	0	30	0	30	ns	1
T _{CLOF}	DEN, AD15:0 (AD7:0, A15:8)	0	30	0	35	ns	1

AC SPECIFICATIONS

Symbol	Parameter	13 MHz		8 MHz		Units	Notes	
Cymbol	i di difetter	Min	Max	Min	Max	onito	Notes	
SYNCHRONOUS INPUTS								
T _{CHIS}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY CTS1:0, P2.6, P2.7	20		25		ns	1, 9	
T _{CHIH}	TEST, NMI, INT4:0, T1:0IN, BCLK1:0, READY, CTS1:0	3		3		ns	1, 9	
T _{CLIS}	AD15:0 (AD7:0), READY	20		25		ns	1, 10	
T _{CLIH}	READY, AD15:0 (AD7:0)	3		3		ns	1, 10	
T _{CLIS}	HOLD	20		25		ns	1, 9	
T _{CLIH}	HOLD	3		3		ns	1, 9	

AC Characteristics—80L186EB13/80L186EB8 (Continued)

NOTES:

1. See AC Timing Waveforms, for waveforms and definition.

- See AC Timing Waveforms, for waveforms and definition.
 Measured at V_{IH} for high time, V_{IL} for low time.
 Only required to guarantee I_{CC}. Maximum limits are bounded by T_C, T_{CH} and T_{CL}.
 Specified for a 50 pF load, see Figure 13 for capacitive derating information.
 Specified for a 50 pF load, see Figure 14 for rise and fall times outside 50 pF.
 See Figure 14 for rise and fall times.
 T_{CHOV1} applies to BHE (RFSH), LOCK and A19:16 only after a HOLD release.
 T_{CHOV2} applies to RD and WR only after a HOLD release.
 Setup and Hold are required to guarantee recognition.

10. Setup and Hold are required for proper operation.



AC SPECIFICATIONS (Continued)

Relative Timin	IGS (80C186EB25, 20, 13/80)	L186EB16, 13, 8)

Symbol	Parameter	Min	Мах	Units	Notes
RELATIVE	TIMINGS				
T _{LHLL}	ALE Rising to ALE Falling	T — 15		ns	
T _{AVLL}	Address Valid to ALE Falling	¹⁄₂T − 10		ns	
T _{PLLL}	Chip Selects Valid to ALE Falling	¹⁄₂T − 10		ns	1
T _{LLAX}	Address Hold from ALE Falling	¹⁄₂T − 10		ns	
T _{LLWL}	ALE Falling to WR Falling	¹⁄₂T − 15		ns	1
T _{LLRL}	ALE Falling to RD Falling	¹⁄₂T − 15		ns	1
T _{WHLH}	WR Rising to ALE Rising	¹⁄₂T − 10		ns	1
T _{AFRL}	Address Float to RD Falling	0		ns	
T _{RLRH}	RD Falling to RD Rising	(2*T) — 5		ns	2
T _{WLWH}	WR Falling to WR Rising	(2*T) — 5		ns	2
T _{RHAV}	RD Rising to Address Active	T — 15		ns	
T _{WHDX}	Output Data Hold after WR Rising	T — 15		ns	
T _{WHPH}	WR Rising to Chip Select Rising	¹⁄₂T − 10		ns	1
T _{RHPH}	RD Rising to Chip Select Rising	¹⁄₂T − 10		ns	1
T _{PHPL}	$\overline{\text{CS}}$ Inactive to $\overline{\text{CS}}$ Active	¹⁄₂T − 10		ns	1
TOVRH	ONCE Active to RESIN Rising	Т		ns	3
T _{RHOX}	ONCE Hold from RESIN Rising	Т		ns	3

NOTES:

Assumes equal loading on both pins.
 Can be extended using wait states.
 Not tested

AC SPECIFICATIONS (Continued)

Symbol	Parameter	Min	Max	Unit	Notes
T _{XLXL}	TXD Clock Period	T (n + 1)		ns	1, 2
T _{XLXH}	TXD Clock Low to Clock High (n > 1)	2T — 35	2T + 35	ns	1
T _{XLXH}	TXD Clock Low to Clock High (n = 1)	T — 35	T + 35	ns	1
T _{XHXL}	TXD Clock High to Clock Low (n > 1)	(n — 1) T — 35	(n - 1) T + 35	ns	1, 2
T _{XHXL}	TXD Clock High to Clock Low ($n = 1$)	T — 35	T + 35	ns	1
T _{QVXH}	RXD Output Data Setup to TXD Clock High (n $>$ 1)	(n - 1) T - 35		ns	1, 2
T _{QVXH}	RXD Output Data Setup to TXD Clock High (n = 1)	T — 35		ns	1
T _{XHQX}	RXD Output Data Hold after TXD Clock High (n $>$ 1)	2T — 35		ns	1
T _{XHQX}	RXD Output Data Hold after TXD Clock High (n = 1)	T — 35		ns	1
T _{XHQZ}	RXD Output Data Float after Last TXD Clock High		T + 20	ns	1
T _{DVXH}	RXD Input Data Setup to TXD Clock High	T + 20		ns	1
T _{XHDX}	RXD Input Data Hold after TXD Clock High	0		ns	1

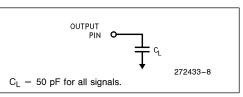
Serial Port Mode 0 Timings (80C186EB25, 20, 13/80L186EB16, 13, 8)

NOTES: 1. See Figure 12 for waveforms. 2. n is the value of the BxCMP register ignoring the ICLK Bit (i.e., ICLK = 0).

AC TEST CONDITIONS

The AC specifications are tested with the 50 pF load shown in Figure 7. See the Derating Curves section to see how timings vary with load capacitance.

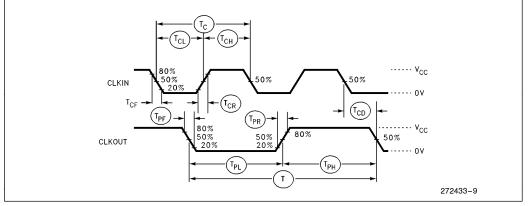
Specifications are measured at the V_{CC}/2 crossing point, unless otherwise specified. See AC Timing Waveforms, for AC specification definitions, test pins, and illustrations.



intel

Figure 7. AC Test Load

AC TIMING WAVEFORMS





80C186EB/80C188EB, 80L186EB/80L188EB

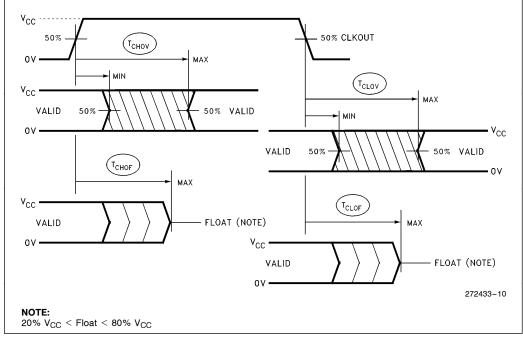


Figure 9. Output Delay and Float Waveform

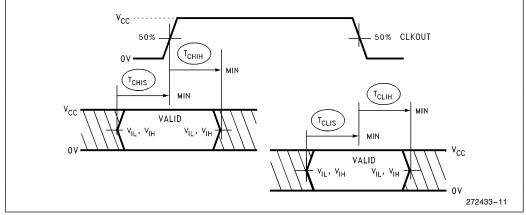


Figure 10. Input Setup and Hold



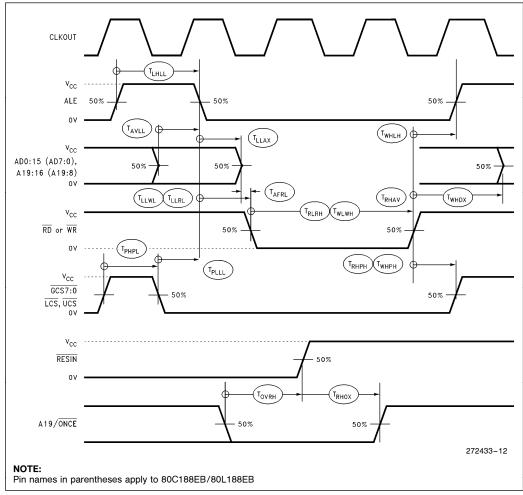


Figure 11. Relative Signal Waveform

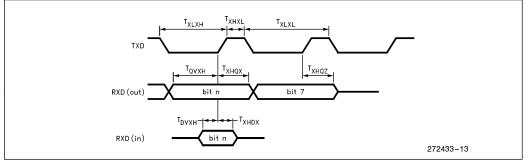


Figure 12. Serial Port Mode 0 Waveform



DERATING CURVES

TYPICAL OUTPUT DELAY VARIATIONS VERSUS LOAD CAPACITANCE

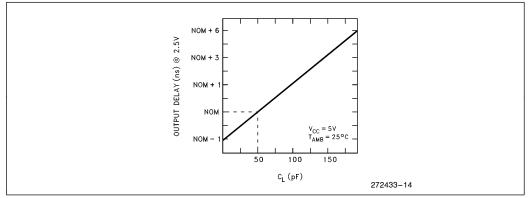


Figure 13

TYPICAL RISE AND FALL VARIATIONS VERSUS LOAD CAPACITANCE

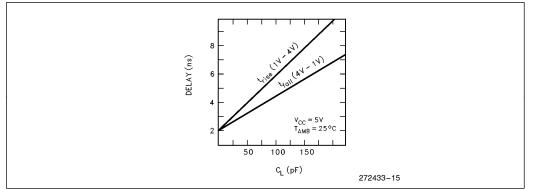


Figure 14



RESET

The processor will perform a reset operation any time the RESIN pin active. The RESIN pin is actually synchronized before it is presented internally, which means that the clock must be operating before a reset can take effect. From a power-on state, RESIN must be held active (low) in order to guarantee correct initialization of the processor. Failure to provide RESIN while the device is powering up will result in unspecified operation of the device.

Figure 14 shows the correct reset sequence when first applying power to the processor. An external clock connected to CLKIN must not exceed the V_{CC} threshold being applied to the processor. This is normally not a problem if the clock driver is supplied with the same V_{CC} that supplies the processor. When attaching a crystal to the device, RESIN must remain active until both V_{CC} and CLKOUT are stable (the length of time is application specific and depends on the startup characteristics of the crystal

circuit). The $\overline{\text{RESIN}}$ pin is designed to operate correctly using an RC reset circuit, but the designer must ensure that the ramp time for V_{CC} is not so long that $\overline{\text{RESIN}}$ is never really sampled at a logic low level when V_{CC} reaches minimum operating conditions.

Figure 16 shows the timing sequence when $\overline{\text{RESIN}}$ is applied after V_{CC} is stable and the device has been operating. Note that a reset will terminate all activity and return the processor to a known operating state. Any bus operation that is in progress at the time $\overline{\text{RESIN}}$ is asserted will terminate immediately (note that most control signals will be driven to their inactive state first before floating).

While RESIN is active, bus signals LOCK, A19/ ONCE, and A18:16 are configured as inputs and weakly held high by internal pullup transistors. Only 19/ONCE can be overdriven to a low and is used to enable ONCE Mode. Forcing LOCK or A18:16 low at any time while RESIN is low is prohibited and will cause unspecified device operation.

80C186EB/80C188EB, 80L186EB/80L188EB

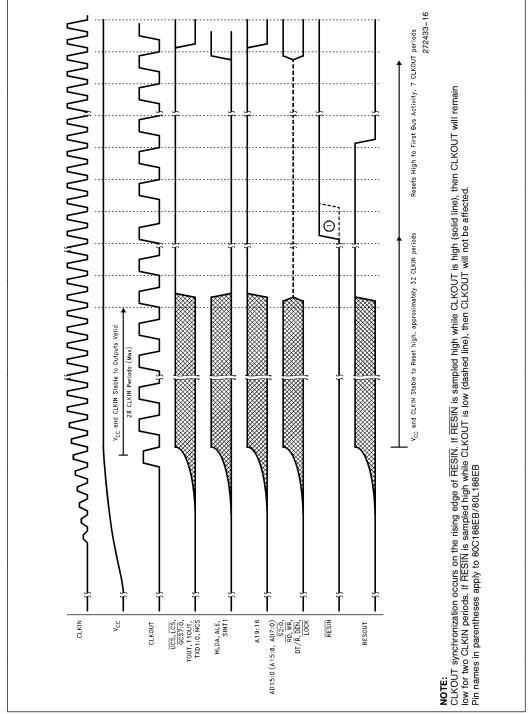


Figure 15. Cold Reset Waveforms

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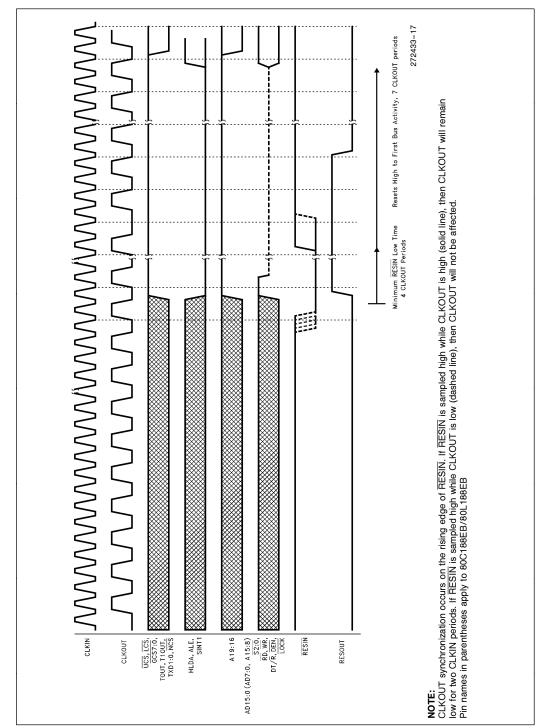


Figure 16. Warm Reset Waveforms

80C186EB/80C188EB, 80L186EB/80L188EB

BUS CYCLE WAVEFORMS

Figures 17 through 23 present the various bus cycles that are generated by the processor. What is shown in the figure is the relationship of the various bus signals to CLKOUT. These figures along with the information present in **AC Specifications** allow the user to determine all the critical timing analysis needed for a given application.

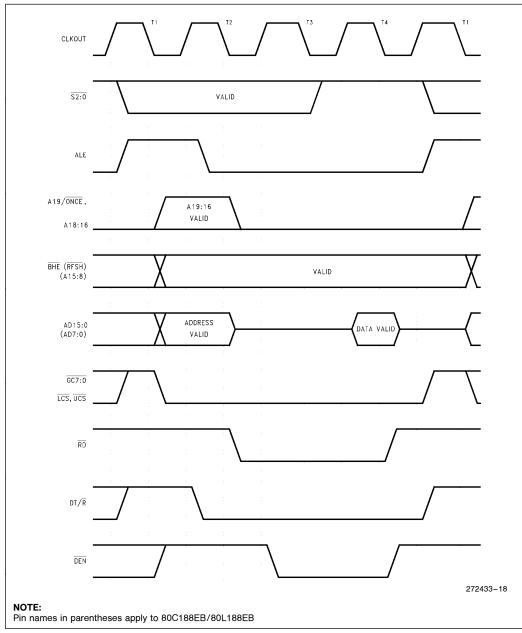


Figure 17. Read, Fetch, and Refresh Cycle Waveforms

PRELIMINARY



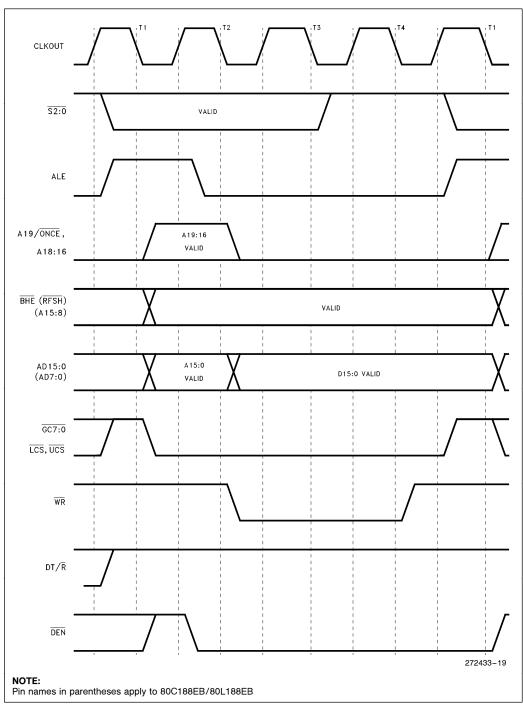
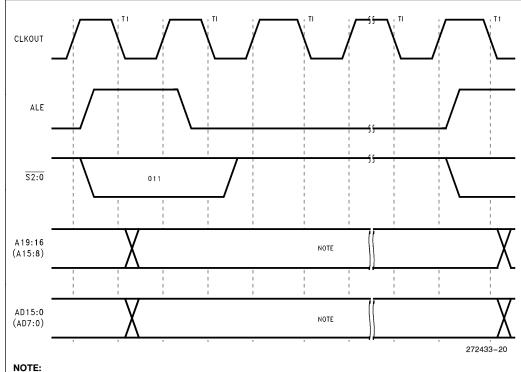


Figure 18. Write Cycle Waveforms



The address driven is typically the location of the next instruction prefetch. Under a majority of instruction sequences the AD15:0 (AD7:0) bus will float, while the A19:16 (A19:8) bus remains driven and all bus control signals are driven to their inactive state.

Pin names in parentheses apply to 80C188EB/80L188EB

Figure 19. Halt Cycle Waveforms



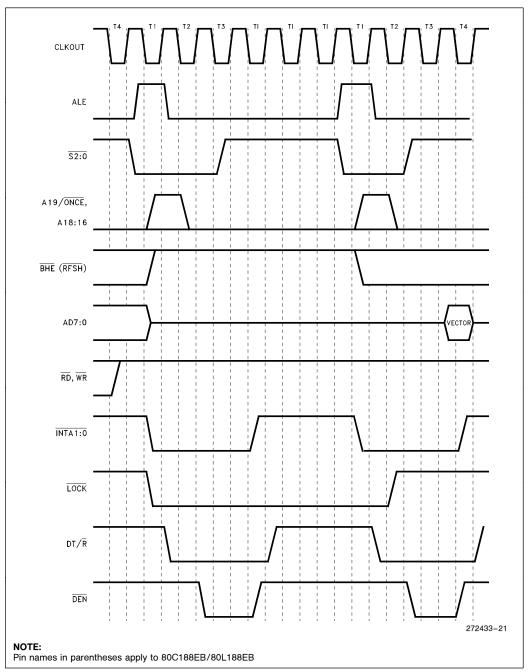


Figure 20. Interrupt Acknowledge Cycle Waveform

80C186EB/80C188EB, 80L186EB/80L188EB

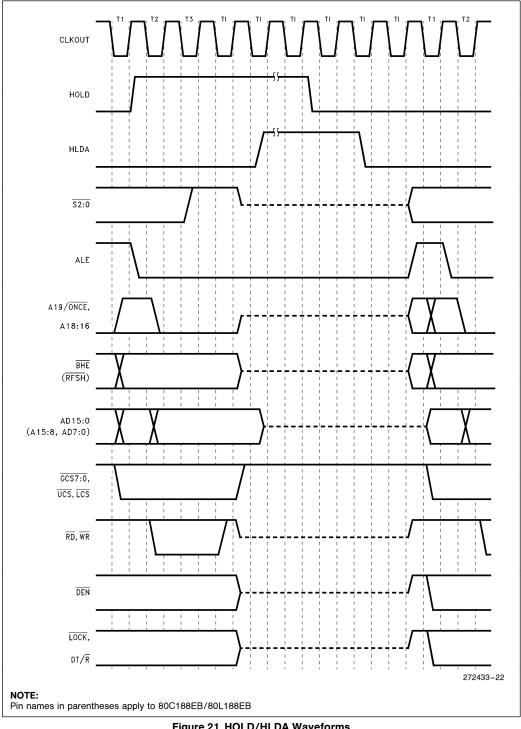
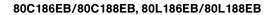


Figure 21. HOLD/HLDA Waveforms





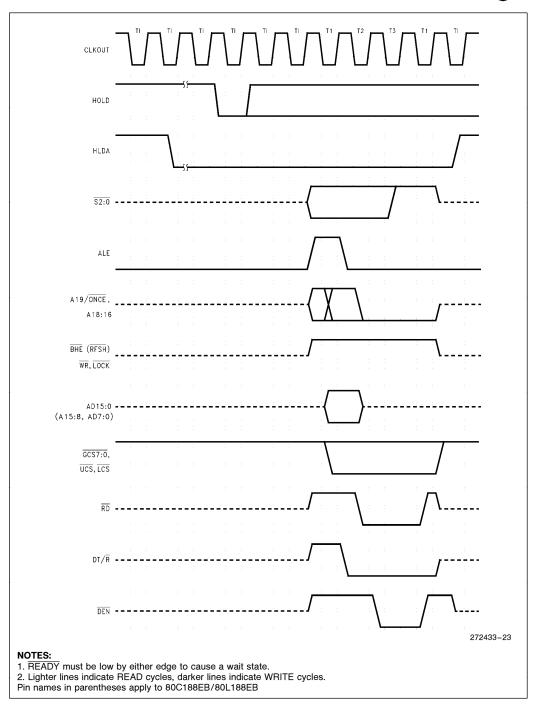


Figure 22. Refresh during Hold Acknowledge

80C186EB/80C188EB, 80L186EB/80L188EB

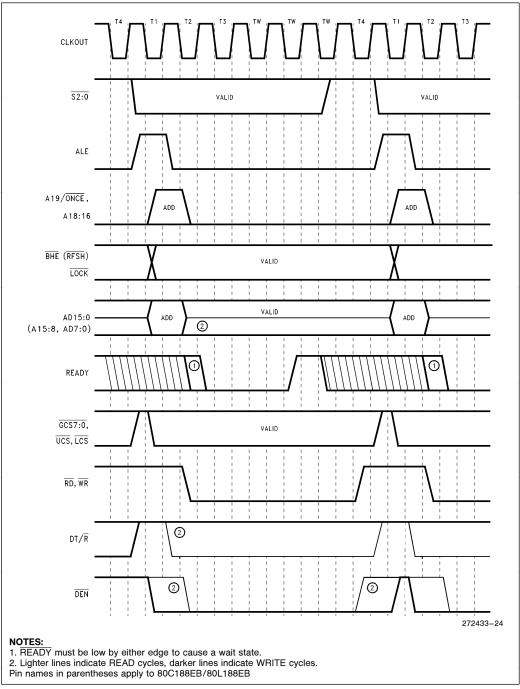


Figure 23. Ready Waveforms



EXECUTION TIMINGS

A determination of program execution timing must consider the bus cycles necessary to prefetch instructions as well as the number of execution unit cycles necessary to execute instructions. The following instruction timings represent the **minimum** execution time in clock cycles for each instruction. The timings given are based on the following assumptions:

- The opcode, along with any data or displacement required for execution of a particular instruction, has been prefetched and resides in the queue at the time it is needed.
- · No wait states or bus HOLDs occur.
- All word-data is located on even-address boundaries (80C186EB only).

All jumps and calls include the time required to fetch the opcode of the next instruction at the destination address.

All instructions which involve memory accesses can require one or two additional clocks above the minimum timings shown due to the asynchronous handshake between the bus interface unit (BIU) and execution unit.

With a 16-bit BIU, the 80C186EB has sufficient bus performance to ensure that an adequate number of prefetched bytes will reside in the queue (6 bytes) most of the time. Therefore, actual program execution time will not be substantially greater than that derived from adding the instruction timings shown.

The 80C188EB 8-bit BIU is limited in its performance relative to the execution unit. A sufficient number of prefetched bytes may not reside in the prefetch queue (4 bytes) much of the time. Therefore, actual program execution time will be substantially greater than that derived from adding the instruction timings shown.

INSTRUCTION SET SUMMARY

Function	Format					80C188EB Clock Cycles	Comments
DATA TRANSFER MOV = Move:							
Register to Register/Memory	1000100w	mod reg r/m			2/12	2/12*	
Register/memory to register	1000101w	mod reg r/m			2/9	2/9*	
Immediate to register/memory	1100011w	mod 000 r/m	data	data if w = 1	12/13	12/13	8/16-bit
Immediate to register	1011w reg	data	data if w = 1]	3/4	3/4	8/16-bit
Memory to accumulator	1010000w	addr-low	addr-high]	8	8*	
Accumulator to memory	1010001w	addr-low	addr-high]	9	9*	
Register/memory to segment register	10001110	mod 0 reg r/m			2/9	2/13	
Segment register to register/memory	10001100	mod 0 reg r/m			2/11	2/15	
PUSH = Push:							
Memory	11111111	mod 1 1 0 r/m			16	20	
Register	01010 reg				10	14	
Segment register	0 0 0 reg 1 1 0				9	13	
Immediate	011010s0	data	data if s=0		10	14	
PUSHA = Push All	01100000				36	68	
POP = Pop:							
Memory	10001111	mod 0 0 0 r/m			20	24	
Register	01011 reg				10	14	
Segment register	0 0 0 reg 1 1 1	(reg≠01)			8	12	
POPA = Pop All	01100001				51	83	
XCHG = Exchange:							
Register/memory with register	1000011w	mod reg r/m			4/17	4/17*	
Register with accumulator	10010 reg				3	3	
IN = Input from:							
Fixed port	1110010w	port			10	10*	
Variable port	1110110w				8	8*	
OUT = Output to:			1				
Fixed port	1110011w	port			9	9*	
Variable port	1110111w				7	7*	
XLAT = Translate byte to AL	11010111				11	15	
LEA = Load EA to register	10001101	mod reg r/m			6	6	
LDS = Load pointer to DS	11000101	mod reg r/m	(mod≠11)		18	26	
LES = Load pointer to ES	11000100	mod reg r/m	(mod≠11)		18	26	
LAHF = Load AH with flags	10011111				2	2	
SAHF = Store AH into flags	10011110				3	3	
PUSHF = Push flags	10011100				9	13	
POPF = Pop flags	10011101				8	12	

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE:

*Clock cycles shown for byte transfers. For word operations, add 4 clock cycles for all memory transfers.

PRELIMINARY



INSTRUCTION SET SUMMARY (Continued)

Function		Fo	rmat		80C186EB Clock Cycles	80C188EB Clock Cycles	Comments
DATA TRANSFER (Continued) SEGMENT = Segment Override:							
CS	00101110				2	2	
SS	00110110				2	2	
DS	00111110				2	2	
ES	00100110				2	2	
ARITHMETIC	00100110	J			-		
ADD = Add:						0/10*	
Reg/memory with register to either	00000dw	mod reg r/m			3/10	3/10*	
Immediate to register/memory	10000sw	mod 0 0 0 r/m	data	data if s w=01	4/16	4/16*	
Immediate to accumulator	0000010w	data	data if w = 1	J	3/4	3/4	8/16-bit
ADC = Add with carry:						0/10*	
Reg/memory with register to either	000100dw	mod reg r/m			3/10	3/10*	
Immediate to register/memory	10000sw	mod 0 1 0 r/m	data	data if s w=01	4/16	4/16*	
Immediate to accumulator	0001010w	data	data if $w = 1$	J	3/4	3/4	8/16-bit
INC = Increment:					0/15	0/15*	
Register/memory	1111111w	mod 0 0 0 r/m			3/15	3/15*	
Register	01000 reg	J			3	3	
SUB = Subtract:	0010104	mod rog r/m			2/10	2/10*	
Reg/memory and register to either	001010dw	mod reg r/m			3/10	3/10*	
Immediate from register/memory	10000sw	mod 1 0 1 r/m	data	data if s w=01	4/16	4/16*	0//01/1
Immediate from accumulator	0010110w	data	data if $w = 1$	J	3/4	3/4	8/16-bit
SBB = Subtract with borrow:	000110dw	mod reg r/m			3/10	3/10*	
Reg/memory and register to either			4-4-	data ita un Od			
Immediate from register/memory	10000sw	mod 0 1 1 r/m	data	data if s w=01	4/16	4/16*	0 (40 bit
Immediate from accumulator DEC = Decrement	0001110w	data	data if w = 1	J	3/4	3/4*	8/16-bit
Register/memory	1111111w	mod 0 0 1 r/m			3/15	3/15*	
Register	01001 reg				3	3	
CMP = Compare:		1					
Register/memory with register	0011101w	mod reg r/m			3/10	3/10*	
Register with register/memory	0011100w	mod reg r/m			3/10	3/10*	
Immediate with register/memory	100000sw	mod 1 1 1 r/m	data	data if s w=01	3/10	3/10*	
Immediate with accumulator	0011110w	data	data if $w = 1$]	3/4	3/4	8/16-bit
NEG = Change sign register/memory	1111011w	mod 0 1 1 r/m		,	3/10	3/10*	
AAA = ASCII adjust for add	00110111				8	8	
DAA = Decimal adjust for add	00100111				4	4	
AAS = ASCII adjust for subtract	00111111				7	7	
DAS = Decimal adjust for subtract	00101111				4	4	
-] 			4	4	
MUL = Multiply (unsigned):	1111011w	mod 100 r/m			00.00		
Register-Byte Register-Word					26–28 35–37	26–28 35–37	
Memory-Byte Memory-Word					32-34 41-43	32-34 41-43*	

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE: *Clock cycles shown for byte transfers. For word operations, add 4 clock cycles for all memory transfers.

80C186EB/80C188EB, 80L186EB/80L188EB

INSTRUCTION SET SUMMARY (Continued)

Function	Format					80C188EB Clock Cycles	Comments
ARITHMETIC (Continued)	(1				
IMUL = Integer multiply (signed): Register-Byte Register-Word Memory-Byte Memory-Word	<u>1111011w</u>	mod 1 0 1 r/m			25–28 34–37 31–34 40–43	25–28 34–37 31–34 40–43*	
IMUL = Integer Immediate multiply (signed)	011010s1	mod reg r/m	data	data if s=0	22-25/ 29-32	22-25/ 29-32	
DIV = Divide (unsigned):	1111011w	mod 1 1 0 r/m					
Register-Byte Register-Word Memory-Byte Memory-Word					29 38 35 44	29 38 35 44*	
IDIV = Integer divide (signed):	1111011w	mod 1 1 1 r/m					
Register-Byte Register-Word Memory-Byte Memory-Word					44–52 53–61 50–58 59–67	44–52 53–61 50–58 59–67*	
AAM = ASCII adjust for multiply	11010100	00001010			19	19	
AAD = ASCII adjust for divide	11010101	00001010			15	15	
CBW = Convert byte to word	10011000]			2	2	
CWD = Convert word to double word	10011001]			4	4	
LOGIC Shift/Rotate Instructions:							
Register/Memory by 1	1101000w	mod TTT r/m			2/15	2/15	
Register/Memory by CL	1101001w	mod TTT r/m			5+n/17+n	5+n/17+n	
Register/Memory by Count	1100000w	mod TTT r/m	count		5+n/17+n	5+n/17+n	
AND = And:		TTT Instruction 000 ROL 001 ROR 010 RCL 011 RCR 100 SHL/SAL 101 SHR 111 SAR					
Reg/memory and register to either	001000dw	mod reg r/m			3/10	3/10*	
Immediate to register/memory	1000000w	mod 1 0 0 r/m	data	data if w = 1	4/16	4/16*	
Immediate to accumulator	0010010w	data	data if w=1		3/4	3/4*	8/16-bit
TEST = And function to flags, no resu	ult:						
Register/memory and register	1000010w	mod reg r/m			3/10	3/10*	
Immediate data and register/memory	1111011w	mod 0 0 0 r/m	data	data if w = 1	4/10	4/10*	
Immediate data and accumulator	1010100w	data	data if w = 1		3/4	3/4	8/16-bit
OR=Or:							
Reg/memory and register to either	000010dw	mod reg r/m			3/10	3/10*	
Immediate to register/memory	100000w	mod 0 0 1 r/m	data	data if w = 1	4/16	4/16*	
Immediate to accumulator	0000110w	data	data if w = 1		3/4	3/4*	8/16-bit

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE: *Clock cycles shown for byte transfers. For word operations, add 4 clock cycles for all memory transfers.

PRELIMINARY



INSTRUCTION SET SUMMARY (Continued)

Function		Fo	rmat		80C186EB Clock Cycles	80C188EB Clock Cycles	Comments
LOGIC (Continued) XOR = Exclusive or:							
Reg/memory and register to either	001100dw	mod reg r/m			3/10	3/10*	
Immediate to register/memory	100000w	mod 1 1 0 r/m	data	data if w = 1	4/16	4/16*	
Immediate to accumulator	0011010w	data	data if w = 1]	3/4	3/4	8/16-bit
NOT = Invert register/memory	1111011w	mod 0 1 0 r/m		-	3/10	3/10*	
STRING MANIPULATION							
MOVS = Move byte/word	1010010w				14	14*	
CMPS = Compare byte/word	1010011w				22	22*	
SCAS = Scan byte/word	1010111w				15	15*	
LODS = Load byte/wd to AL/AX	1010110w				12	12*	
STOS = Store byte/wd from AL/AX	1010101w				10	10*	
INS = Input byte/wd from DX port	0110110w				14	14	
OUTS = Output byte/wd to DX port	0110111w				14	14	
Repeated by count in CX (REP/REPE/	REPZ/REPNE/REP	NZ)					
MOVS = Move string	11110010	1010010w			8+8n	8+8n*	
CMPS = Compare string	1111001z	1010011w			5+22n	5+22n*	
SCAS = Scan string	1111001z	1010111w			5+15n	5+15n*	
LODS = Load string	11110010	1010110w			6+11n	6+11n*	
STOS = Store string	11110010	1010101w			6+9n	6+9n*	
INS = Input string	11110010	0110110w			8+8n	8+8n*	
OUTS = Output string	11110010	0110111w			8+8n	8+8n*	
CONTROL TRANSFER	11110010	0110111			0 1 011	0 1 011	
CALL = Call:							
Direct within segment	11101000	disp-low	disp-high]	15	19	
Register/memory	11111111	mod 0 1 0 r/m			13/19	17/27	
indirect within segment							
Direct intersegment	10011010	segmer	t offset]	23	31	
		segment	selector]			
Indirect intersegment	11111111	mod 0 1 1 r/m	(mod ≠ 11)		38	54	
JMP = Unconditional jump:		·,					
Short/long	11101011	disp-low			14	14	
Direct within segment	11101001	disp-low	disp-high]	14	14	
Register/memory indirect within segment	11111111	mod 1 0 0 r/m			11/17	11/21	
Direct intersegment	11101010	segmer]	14	14	
		segment	selector	J			
Indirect intersegment	11111111	mod 1 0 1 r/m	(mod ≠ 11)		26	34	

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE: *Clock cycles shown for byte transfers. For word operations, add 4 clock cycles for all memory transfers.

INSTRUCTION SET SUMMARY (Continued)

Function		Format			80C186EB Clock Cycles	80C188EB Clock Cycles	Comments
CONTROL TRANSFER (Continued) RET = Return from CALL:							
Within segment	11000011				16	20	
Within seg adding immed to SP	11000010	data-low	data-high]	18	22	
Intersegment	11001011				22	30	
Intersegment adding immediate to SP	11001010	data-low	data-high]	25	33	
JE/JZ = Jump on equal/zero	01110100	disp			4/13	4/13	JMP not
JL/JNGE = Jump on less/not greater or equal	01111100	disp			4/13	4/13	taken/JMP taken
JLE/JNG = Jump on less or equal/not greater	01111110	disp			4/13	4/13	laken
JB/JNAE = Jump on below/not above or equal	01110010	disp			4/13	4/13	
JBE/JNA = Jump on below or equal/not above	01110110	disp			4/13	4/13	
JP/JPE = Jump on parity/parity even	01111010	disp			4/13	4/13	
JO = Jump on overflow	01110000	disp			4/13	4/13	
JS = Jump on sign	01111000	disp			4/13	4/13	
JNE/JNZ = Jump on not equal/not zero	01110101	disp			4/13	4/13	
JNL/JGE = Jump on not less/greater or equal	01111101	disp			4/13	4/13	
JNLE/JG = Jump on not less or equal/greater	01111111	disp			4/13	4/13	
JNB/JAE = Jump on not below/above or equal	01110011	disp			4/13	4/13	
JNBE/JA = Jump on not below or equal/above	01110111	disp			4/13	4/13	
JNP/JPO = Jump on not par/par odd	01111011	disp			4/13	4/13	
JNO = Jump on not overflow	01110001	disp			4/13	4/13	
JNS = Jump on not sign	01111001	disp			4/13	4/13	
JCXZ = Jump on CX zero	11100011	disp			5/15	5/15	
LOOP = Loop CX times	11100010	disp			6/16	6/16	LOOP not
LOOPZ/LOOPE = Loop while zero/equal	11100001	disp			6/16	6/16	taken/LOOI taken
LOOPNZ/LOOPNE = Loop while not zero/equal	11100000	disp			6/16	6/16	takon
ENTER = Enter Procedure	11001000	data-low	data-high	L			
L = 0					15	19	
L = 1 L > 1					25 22+16(n-1)	29 26+20(n-1)	
LEAVE = Leave Procedure	11001001				8	8	
INT = Interrupt:							
Type specified	11001101	type			47	47	
Туре 3	11001100				45	45	if INT. taken
INTO = Interrupt on overflow	11001110				48/4	48/4	if INT. not taken
IRET = Interrupt return	11001111				28	28	
BOUND = Detect value out of range	01100010	mod reg r/m			33-35	33-35	

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE:

*Clock cycles shown for byte transfers. For word operations, add 4 clock cycles for all memory transfers.

PRELIMINARY



INSTRUCTION SET SUMMARY (Continued)

Function	Format	80C186EB Clock Cycles	80C188EB Clock Cycles	Comments
PROCESSOR CONTROL				
CLC = Clear carry	1111000	2	2	
CMC = Complement carry	11110101	2	2	
STC = Set carry	1 1 1 1 1 0 0 1	2	2	
CLD = Clear direction	1111100	2	2	
STD = Set direction	1111101	2	2	
CLI = Clear interrupt	1111010	2	2	
STI = Set interrupt	1111011	2	2	
HLT = Halt	11110100	2	2	
WAIT = Wait	10011011	6	6	if $\overline{\text{TEST}} = 0$
LOCK = Bus lock prefix	11110000	2	2	
NOP = No Operation	1001000	3	3	
	(TTT LLL are opcode to processor extension)			

Shaded areas indicate instructions not available in 8086/8088 microsystems.

NOTE:

*Clock cycles shown for byte transfers. For word operations, add 4 clock cycles for all memory transfers.

FOOTNOTES

		e Address (EA) of the memory operand	reg	Register
is compl	uted	according to the mod and r/m fields:	00	ES
if mod		11 then r/m is treated as a REG field	01	CS
if mod	=	00 then DISP = 0^* , disp-low and disp-	10	SS
if mod	_	high are absent 01 then DISP = disp-low sign-ex-	11	DS
ii mou		tended to 16-bits, disp-high is absent	DEC is assigned assortin	a to the following toble:
if mod	=	10 then $DISP = disp-high: disp-low$	REG is assigned accordin	• •
if r/m	=	000 then $EA = (BX) + (SI) + DISP$	16-Bit (w = 1)	8-Bit (w = 0)
if r/m	=	001 then $EA = (BX) + (DI) + DISP$	000 AX	000 AL
if r/m	=	010 then $EA = (BP) + (SI) + DISP$	001 CX	001 CL
if r/m	=	011 then $EA = (BP) + (DI) + DISP$	010 DX	010 DL
if r/m	=	100 then EA = (SI) + DISP	011 BX	011 BL
if r/m if r/m	=	101 then EA = (DI) + DISP 110 then EA = (BP) + DISP*	100 SP	100 AH
if r/m	=	111 then EA = (BX) + DISP	101 BP	101 CH
			110 SI	110 DH
DISP fol	lows	a 2nd byte of instruction (before data if	111 DI	111 BH

DISP follows 2nd byte of instruction (before data if required)

*except if mod = 00 and r/m = 110 then EA = disp-high: disp-low.

EA calculation time is 4 clock cycles for all modes, and is included in the execution times given whenever appropriate.

Segment Override Prefix

0 0 1 reg 1 1 0

The physical addresses of all operands addressed by the BP register are computed using the SS segment register. The physical addresses of the destination operands of the string primitive operations (those addressed by the DI register) are computed using the ES segment, which may not be overridden.

reg is assigned according to the following:

Segment

80C186EB/80C188EB, 80L186EB/80L188EB

ERRATA

An 80C186EB/80L186EB with a STEPID value of 0001H has the following known errata. A device with a STEPID of 0001H can be visually identified by the **presence** of an **"A"** alpha character next to the FPO number. The FPO number location is shown in Figures 4, 5 and 6.

- 1. A19/ONCE is not latched by the rising edge of RESIN. A19/ONCE must remain active (LOW) at all times to remain in the ONCE Mode. Removing A19/ONCE after RESIN is high will return all output pins to a driving state, however, the 80C186EB will remain in a reset state.
- During interrupt acknowledge (INTA) bus cycles, the bus controller will ignore the state of the READY pin if the previous bus cycle ignored the state of the READY pin. This errata can only occur if the Chip-Select Unit is being used. All active chip-selects must be programmed to use READY (RDY bit must be programmed to a 1) if waitstates are required for INTA bus cycles.
- CLKOUT will transition off the rising edge of CLKIN rather than the falling edge of CLKIN. This does not affect any bus timings other than T_{CD}.
- RESIN has a hysterisis of only 130 mV. It is recommended that RESIN be driven by a Schmitt triggered device to avoid processor lockup during reset using an RC circuit.

5. SINT1 will only go active for one clock period when a receive or transmit interrupt is pending (i.e., it does not remain active until the S1STS register is read). If SINT1 is to be connected to any of the processor interrupt lines (INT0–INT4), then it must be latched by user logic.

An 80C186EB/80L186EB with a STEPID value of 0001H or 0002H has the following known errata. A device with a STEPID of 0002H can be visually identified by noting the presence of a "B", "C", "D", or "E" alpha character next to the FPO number. The FPO number location is shown in Figures 4, 5 and 6.

1. An internal condition with the interrupt controller can cause no acknowledge cycle on the INTA1 line in response to INT1. This errata only occurs when Interrupt 1 is configured in cascade mode and a higher priority interrupt exists. This errata will not occur consistantly, it is dependent on interrupt timing.

REVISION HISTORY

This data sheet replaces the following data sheets:

270803-004 80C186EB 270885-003 80C188EB 270921-003 80L186EB 270920-003 80L188EB 272311-001 SB80C188EB/SB80L188EB 272312-001 SB80C186EB/SB80L186EB